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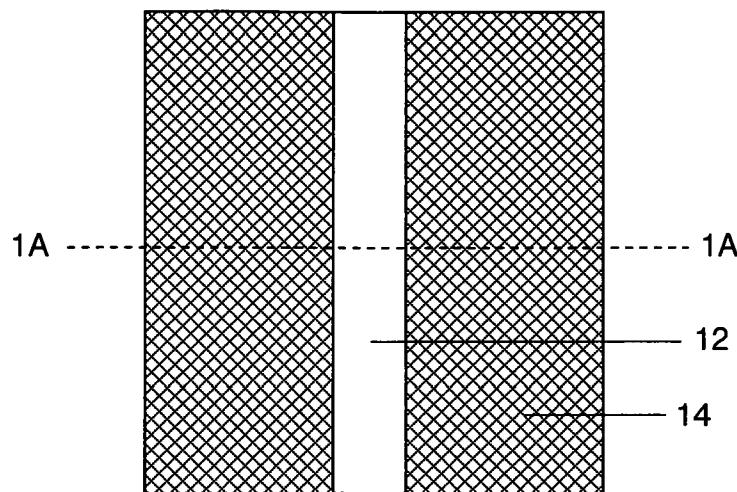


FIG. 1

(57) Abstract: The invention relates to a process for forming a stacked transparent structure comprising providing a support, coating one side of said support with a multicolored mask, coating the other side of the support with a layer curable by visible light, and exposing the light-curable layer through the mask with visible light to cure the layer curable by light in exposed portions to form a cured pattern.

## **MULTICOLOR MASK**

### **FIELD OF THE INVENTION**

The invention relates to a colored masking technique useful for  
5 forming electrical components.

### **BACKGROUND OF THE INVENTION**

Manufacture of many electronic components, including flat panel displays, RFID tags, and various sensing applications, relies upon accurately patterning layers of electrically active materials applied to a relatively large substrate. These products are composed of several layers of different patterned materials, where it is important that the layers be in specific registration. The reasons for patterning accuracy are twofold. First of all, patterned features must be reproduced across large areas of a substrate while having precise control over their dimensions. Secondly, products built with these features typically are composed of several layers of different, but interacting patterned layers, where it is important that the layers be in specific vertical registration, referred to as layer alignment.

Traditionally, the precise layer alignment required for fabrication of electronic components and devices is accomplished using conventional photolithography. An electrically active layer and a photoresist layer are deposited on a substrate, the position of an existing pattern on the substrate is detected and an exposure mask is aligned to that existing pattern. The photoresist is exposed, developed, and the electrically active material is etched. Small variations in temperature and humidity in this precise operation may be enough to introduce alignment errors; rigid glass substrates are used with stringent environmental controls to reduce these variations. At the other extreme, conventional printing techniques such as offset lithography, flexography, and gravure printing also apply multiple layers at extremely high speeds, although at substantially lower overlay accuracy.

30 There is a growing interest in advancing printing technology toward fabrication of thin film electrical components (such as TFTs) on flexible or

plastic substrates. These substrates would be mechanically robust, lighter weight, and eventually lead to lower cost manufacturing by enabling roll-to-roll processing. In spite of the potential advantages of flexible substrates, there are many issues affecting the performance and ability to perform alignments of 5 transistor components across typical substrate widths up to one meter or more. The overlay accuracy achievable using traditional photolithography equipment can be seriously impacted by substitution of a flexible plastic substrate for the rigid glass substrates traditionally employed. Dimensional stability, particularly as the process temperature approaches the glass transition temperature (Tg) of substrate 10 materials, water and solvent swelling, anisotropic distortion, and stress relaxation are all key parameters in which plastic supports are inferior to glass.

Typical fabrication involves sequential deposition and patterning steps. Three types of registration errors are common in these fabrication processes: fixed errors, scale errors, and local misalignments. The fixed error, 15 which refers to a uniform shift of one pattern to another, is typically dominated by the details of the motion control system. Specifically, mechanical tolerances and details of the system integration ultimately dictate how accurately the substrate may be aligned to a mask, or how accurately an integrated print device may be positioned with respect to a registration mark on a moving web. In addition to 20 fixed errors, scale errors may also be substantial. Errors in pattern scale are cumulative across the substrate and arise from support dimensional change, thermal expansion, and angular placement errors of the substrate with the patterning device. Although the motion control system impacts angular placement, pattern scale mismatch is largely driven by the characteristics of the 25 support. Thermal expansion, expansion from humidity or solvent exposure, shrinkage from high temperature exposure, and stress relaxation (creep) during storage of the support all contribute to pattern scale errors. Further, local pattern mismatch arising from nonisotropic deformations may also occur, particularly since the conveyance process involves applying tension. A flexible support used 30 in roll-to-roll manufacturing will typically stretch in the conveyance direction and narrow in width.

There are several approaches to address the registration problem for fabrication of electronics on flexible substrates, but at this point a leading methodology has yet to emerge. Attach/detach technology has been explored by French et al., wherein a flexible substrate is laminated to a rigid carrier and runs through a traditional photolithographic process (I. French et al., "Flexible Displays and Electronics Made in AM-LCD Facilities by the EPLaRTM Process" SID 07 Digest, pp. 1680-1683 (2007)). Unfortunately, these technologies ultimately produce a flexible electronics component, but with the cost structure of current glass based processing.

US Patent Publication No. 2006/0063351 by Jain describes coating the front side and back side of a substrate with one or more resist layers that may be activated simultaneously to impart distinct pattern images within each resist layer. The precoated substrate is inserted between a set of prealigned masks, or alternatively a dual-wavelength maskless direct-laser-writing lithography system is used, to simultaneously expose the front and back sides.

Active alignment systems to detect previously existing patterns and compensation schemes for deformation have also been suggested in US Patent No. 7,100,510, by Brost et al. With this approach, instead of attaining accurate pattern overlay by maintaining tight specs on support dimensional stability and strict environmental control, the motion control system performs multiple alignments per substrate to compensate for distortion. The proposed solution of Brost et al., to adapt traditional printing equipment for active alignment, may be viewed as exchanging the lens, mask, and lamp of a modern stepper with an integrated print device. It is difficult to imagine significant equipment cost difference or throughput advantage, particularly if the added task of distortion compensation is included. A fabrication cost advantage would likely come primarily from materials usage savings or removal of expensive vacuum deposition steps.

Another approach, which would potentially enable high speed processing with low capital investment, is to employ a self-aligning fabrication process. In a self-aligning process, a template for the most critical alignments in the desired structure is applied in one step to the substrate and from that point

forward alignment of subsequent layers is automatic. Various methods have been described for fabricating self-aligned TFTs. Most of these methods allow self-alignment of one layer to another layer, but do not significantly remove the need for very sophisticated alignment steps between several layers. For example, the 5 gate electrode in some a-Si TFT processes is used as a “mask” to protect the channel area from doping and laser annealing of the silicon on either side of the channel region.

The concept of self-aligned fabrication can be understood from US Patent No. 5,391,507 by Kwasnick et al, US Patent No. 6,338,988 by to Andry et 10 al., and US Patent Publication No. 2004/229411 by Battersby.

One published technique offering the potential for a fully self aligned process that eliminates the need for complex registration is Self-Aligned Imprint Lithography (SAIL), as illustrated in US Patent No. 7,056,834 by Mei et al. In imprint lithography, a variable-thickness resist is prepared on the 15 electronically active layers and a sequencing of chemical etch and materials deposition is matched to controlled erosion of the photoresist to produce TFT structures. There are difficulties with the SAIL process. The first issue is the need for a robust nanoimprint technology for webs. Secondly, the SAIL process requires high accuracy etch depth control, which may not be consistent with a low 20 cost process. Finally, a significant limitation of the SAIL process is that layers produced by the mask cannot be fully independent. As an example, it is particularly challenging to form openings under continuous layers with this approach, an essential element in a matrix backplane design.

There is a growing interest in depositing and patterning thin film 25 semiconductors, dielectrics and conductors on flexible substrates, particularly because these supports would be more mechanically robust, lighter weight, and potentially lead to more economical manufacturing by allowing roll-to-roll processing. The present invention facilitates highly accurate patterning in an advantageous and simple way that solves one or more of the aforesaid problems in 30 the prior art, especially when using flexible substrates.

**PROBLEM TO BE SOLVED BY THE INVENTION**

The problems addressed by the current invention are to reproduce patterned features, even across large areas, while having precise control over the feature dimensions, including registration and alignment, of patterned features that are in different layers. Additionally, it is highly desirable to overcome these problems in a way that does not require expensive equipment or expensive processes.

**SUMMARY OF THE INVENTION**

The invention generally is accomplished by a process for forming a stacked transparent structure comprising providing a support; forming at least a first portion of a multicolored mask on one side of said support; coating the first portion of the multicolor mask with a photopatternable layer sensitive to visible light; and exposing the photopatternable layer through the mask with visible light to form a pattern.

One embodiment of the invention is directed to a process for forming a structure comprising:

- a) providing a transparent support;
- b) forming a multicolor mask having at least a first color pattern on a first side of the support and a second color pattern; and
- c) forming at least two layers of patterned functional materials, each patterned layer formed by:
  - i) coating a layer of a photopatternable material sensitive to visible light on the first side of the support after forming the multicolor mask;
  - ii) exposing the layer of photopatternable material through the multicolor mask with visible light to form a photopattern corresponding to the one of the color patterns of the multicolor mask wherein the photopattern is composed of photopatternable material in a second exposed state that is different from a first as-coated state;
  - iii) depositing a layer of a functional material before or after coating the photopatternable material; and

iv) patterning the functional material using the photopattern such that the resulting patterned functional material corresponds to the color pattern;

5 wherein the first color pattern, support, and at least two layers of patterned functional materials remain in the structure.

### **ADVANTAGEOUS EFFECT OF THE INVENTION**

One advantage of the present invention is that it provides a method for forming aligned layers without the need for expensive alignment equipment and processes. Another advantage is the multicolor mask is prepared directly on 10 the support in color-encoded form ensuring that the correct mask is used.

Additionally, spectrally-sensitized resist materials, sensitive to either red, green or blue light can be used to pattern all layers in a transistor, including a transparent oxide such as a zinc-oxide-containing semiconductor. The multicolor mask has the advantage of containing more independently addressable levels than a 15 grayscale mask and works particularly well for patterning transparent electronic materials.

### **BRIEF DESCRIPTION OF THE DRAWINGS**

The above and other objects, features, and advantages of the present invention will become more apparent when taken in conjunction with the 20 following description and schematic drawings wherein identical reference numerals have been used, where possible, to designate identical or analogous features that are common to the figures, and wherein:

Figs. 1 and 1A are a pattern of blue color absorber on a transparent support;

25 Figs. 2 and 2A shows a pattern of green color absorber on a transparent support;

Figs. 3 and 3A. shows a pattern of red color absorber on a transparent support;

30 Figs. 4 and 4A show the individual color absorber layers in a layered structure on support material forming a multicolor mask;

Figs. 5A-5D show a process for selectively forming a pattern of material registered with the blue color absorber pattern of the multicolor mask;

Figs. 6A-6D show a process for selectively forming a pattern of material registered with the green color absorber pattern of the multicolor mask;

5 Figs. 7A-7D show a process for selectively forming a pattern of material registered with the red color absorber pattern of the multicolor mask;

Figs. 8A-8H show a process where three different patterned structures are selectively formed by changing the color of exposing light through the multicolor mask;

10 Figs. 9A-9F show an example of a liftoff patterning process using a multicolor mask;

Figs. 10A-10F show an example of a selective etch patterning process using a multicolor mask;

15 Figs. 11A-11F show a selective deposition patterning process using a multicolor mask;

Figs. 12A-12H show a possible sequence of exposure, processing, and deposition steps to form a multilayer electronic device using transparent components and a multicolor mask;

20 Figs. 13A-13H show another possible sequence of exposure, processing, and deposition steps to form a multilayer electronic device using transparent components and a multicolor mask;

Figs. 14A-14H show yet another possible sequence of exposure, processing, and deposition steps to form a multilayer electronic device using transparent components and a multicolor mask;

25 Figs. 15A-15B illustrate another embodiment of a multicolor mask of the present invention; and

Figs. 16, 16A, and 16B show another embodiment of a layer electronic device formed using a multicolor mask of the present invention.

#### **DETAILED DESCRIPTION OF THE INVENTION**

30 For ease of understanding, the following terms used herein are described below in more detail.

As utilized herein, the term "front" as applied to the invention article is the side of the support carrying the functional patterned layers; the term "back" as used herein refers to the side of the support opposite to the side carrying the patterned functional layers.

5 "Vertical" means substantially perpendicular to the surface of a substrate.

"Transparent" generally denotes a material or construct that does not absorb a substantial amount of light in the visible portion (and/or infrared portion in certain variants) of the electromagnetic spectrum. In this invention, the 10 transparency of a materials is only with reference to the colors of light that are being used in a particular process step. Transparent means at least 65% of the reference light passes through the member.

15 "Photopatternable" refers to a material that, upon exposure to light, changes in states such as in terms of solubility, tackiness, mechanical strength, permeability to etchants or gases, surface reactivity and/or index of refraction, such that the changed material corresponds to a pattern.

"Positive" refers to a pattern, which contains material in those areas above the colored parts of the photomask.

20 "Negative" refers to a pattern, which contains material in those areas above the transparent parts of the photomask.

"Multicolor mask" refers to the vertically aligned set of color absorbing patterns in the patterned structure. The color patterns of a multicolor mask may be in separate layers or in the same layer.

25 A thin film transistor (TFT) is a likely electronic element that can benefit from the patterning process of this invention. The next three definitions refer specifically to thin film transistors.

30 As used herein, the terms "over," "above," and "under" and the like, with respect to layers in the thin film transistor, refer to the order of the layers with respect to the support, but do not necessarily indicate that the layers are immediately adjacent or that there are no intermediate layers.

"Gate" generally refers to the insulated gate terminal of a three terminal FET when used in the context of a transistor circuit configuration.

The preceding term descriptions are provided solely to aid the reader, and should not be construed to have a scope less than that understood by a 5 person of ordinary skill in the art or as limiting the scope of the appended claims.

The process of this invention can be used to generate any variety of multilayer structures containing patterned layers with fixed vertical registration. This process is therefore capable of producing monolithically integrated structures 10 that can be designed to function as conductors, inductors, capacitors, transistors, diodes, photodiodes, light emitting diodes, and other electronic or optoelectronic components. Furthermore, the patterning technology can be used to simultaneously produce a number of these devices arranged in a way to produce 15 useful electronic circuitry.

Accurate pattern overlay over large areas and on flexible supports 15 is enabled by use of a color-encoded mask, which is prepared directly on the support, in combination with spectrally sensitized photoresists. The color-encoded mask can contain either in one structure, or in multiple portions, all or most of the patterning information for the system. Transparent electronic materials are subsequently deposited in layer-by-layer fashion. Spectrally 20 sensitized photoresists are selectively exposed through the multicolored mask to form photoresist patterns on the front side of the support, vertically aligned to the color mask. Patterning of electrically active or functional layers can be accomplished by using etch, liftoff, or selective deposition process to pattern the gate, dielectric, semiconductor, and source/drain layers. The multicolor mask is 25 part of the substrate, and is formed on either only the side of the active layers or on both sides of the substrate. The multicolor mask can contain pattern information for all of the layers in a process. Fabrication using the present invention can be fully self-aligning, and catastrophic overlay errors arising from dimensional change of supports, web weave, and transport errors can thereby be avoided.

30 In one embodiment of the present invention, the entire multicolor mask remains as part of the final device. In another embodiment of the invention,

only a first portion of the multicolor mask remains in the final device. These embodiments will be better understood with respect to the figures.

The figures and following description illustrate a masking scheme of the current invention. The illustrative example of this description utilizes three masking layers, composed of different color absorbing materials, and utilizes photopatternable materials, sensitive to colored light, to pattern transparent functional layers. The figures are intended to illustrate the present invention and should not be considered limiting. Multicolor masks of two masking layers, as well as multicolor masks of greater than three masking layers are alternative embodiments of the present invention. Additionally, the figures illustrate the color patterns of the multicolor mask as separate layers for descriptive clarity. In other embodiments of the present invention, all of the color patterns to reside in a single layer can be easily understood with respect to the figures in this disclosure. Furthermore, embodiments where a multiple, but not all, color patterns are in a single layer fall within this invention.

Light used for exposing can be panchromatic or colored. Panchromatic light refers to light that has some spectral intensity over the visible spectrum. Panchromatic light should be recognized by one skilled in the art as light is a light that contains multiple colors. Colored light generally refers to light that has high intensity in certain spectral regions and lower intensities in others. Colored light can be described by the wavelength of the maximum intensity ( $\lambda_{\max}$ ) and by the FWHM (full width at half the maximum), or by the bandpass. For light to be considered colored, the ratio of the minimum intensity to the maximum intensity across a given spectral region should be less than 20%, preferably less than 10%.

Referring now to the drawings, Figs. 1-3A show the patterns of three mask layers. Fig. 1 and 1A show the pattern of the first mask layer as a pattern of a blue color absorber (14) on transparent support (12). Fig. 2 and 2A show the pattern of the second mask layer as a pattern of a green color absorber (18) on transparent support (12). Fig. 3 and 3A show the pattern of the third mask layer as a pattern of a red color absorber (16) on transparent support (12). Figs. 4

and 4A show an article 11 composed of individual color absorber layers (14, 16, 18) in a layered structure on support material forming multicolor mask (10). An important aspect of the present invention is that the multicolor mask contains in one structure most or all of the patterning information for the system in a color-encoded form. This is important because the entire article, including support (12) 5 may be exposed to varying temperature, pressure, solvent and humidity treatments during the fabrication and coating steps, naturally leading to variations in dimension (such as shrinkage or thermal expansion) of the support. Web transport systems apply tension to the support, leading to dimensional instability as well. In 10 fact, the lowest cost and potentially cheapest support materials are likely to have a higher degree of dimensional instability. For example, polyester film has a thermal expansion coefficient of 0.0018% per °C, such that a 5° C change will result in a dimensional change of 90 µm over 1 meter. The effect of humidity expansion and thermal expansion need not lead to cumulative and catastrophic 15 alignment errors when a multicolor mask element (10) is provided. Simply, the patterning information is contained in the color absorbing layers that are attached to the support, and thus remain in fixed vertical alignment as the support shrinks or expands and are not impacted by support dimensional change.

Figures 5A-7D show processes for selectively forming patterns of 20 photopatternable material registered with a specific color absorber pattern of multicolor mask (10). The specific pattern to be formed is selected by adjusting the sensitivity distribution of the photopatternable film. A photopatternable layer with a sensitivity to blue, green, or red light is coated on the multicolor mask. This photopatternable layer is exposed with light through the multicolor mask. 25 The color absorbers of the multicolor mask selectively transmit the illuminating light, thereby exposing the photopatternable layer to a pattern of colored light. For example, a cyan mask absorbs red light while transmitting blue and green light. Similarly, a magenta mask absorbs green light while transmitting red and blue light and a yellow mask absorbs blue light while transmitting red and green light. 30 Thus, by combining the properties of such individual masks, a multicolor mask may be formed to provide patterns of selectively transmitted light. The sensitivity

distribution of the photopatternable layer, in a preferred embodiment, is completely contained within the absorption spectrum of one of the color absorbing materials used in multicolor mask (10) and completely isolated from the absorption spectrum of the other color absorbing materials in multicolor mask

5 (10). In a preferred embodiment of the invention, the photopatternable layer contains a polymerizable compound and a photoinitiator responsive only to specific wavelengths of colored light. Absorption of colored light by the photoinitiator initiates the photopolymerization reaction. The photopatternable layer may contain additional components that include but are not limited to

10 polymeric binders, fillers, pigments, surfactants, adhesion modifiers, antioxidants, co-initiators, chain transfer agents, and the like. One convenient way to modify the sensitivity distribution of the photopatternable layer is with the identity of the photoinitiator. The spectral distribution of illuminating light may be specifically selected to minimize effects from unwanted absorption of the color absorbing

15 material and/or unwanted sensitivity of the photopatternable layer. Following exposure, the photopatternable layer is developed. The remaining pattern may be the positive image of the mask layer or a negative image, depending on the type of photopatternable material used. Figs. 5A-7D illustrate the use of a photocurable or negative working photoresist.

20 Figs. 5A-5D show a process for selectively forming a pattern of material registered with the blue color absorber pattern of the multicolor mask. Referring now to Figs. 5A and 5B, there is illustrated a schematic plan view and cross-sectional view of the multicolor mask (10) that has been coated with a blue photopatternable layer (22) and exposed with a light source containing blue light.

25 This light source may be a white light, or panchromatic light, source. In this embodiment, the photopatternable material of the photopatternable layer is negative working. Figs. 5C and 5D show the schematic plan view and cross-sectional view of the resulting structure after the exposed blue-curable film from Fig. 5A has been developed, forming a pattern of blue-cured material (24)

30 registered with the blue color absorber pattern (14) of multicolor mask (10).

Figs. 6A-6D show a process for selectively forming a pattern of material registered with the green color absorber pattern of the multicolor mask. Figs. 6A and 6B show schematic plan view and cross-sectional view of the multicolor mask (10) that has been coated with a green photopatternable layer (30) and exposed with a light source containing green light. This light source may be a white light, or panchromatic light, source. In this embodiment, the photopatternable material of the photopatternable layer is negative working. Figs. 6C and 6D show a schematic plan view and cross-sectional view of the resulting structure after the exposed green-curable film from Fig. 6A has been developed, forming a pattern of green-cured material (32) registered with the green color absorber pattern (18) of multicolor mask (10).

Figs. 7A-7D show a process for selectively forming a pattern of material registered with the red color absorber pattern of the multicolor mask. Figs. 7A and 7B show a schematic plan view and cross-sectional view of the multicolor mask (10) that has been coated with a red curable film (38) and exposed with a light source containing red light. This light source may be a white light, or panchromatic light, source. In this embodiment, the photopatternable material of the photopatternable layer is negative working. Figs. 7C and 7D show a schematic plan view and cross-sectional view of the resulting structure after the exposed red-curable film from Fig. 7A has been developed, forming a pattern of red-cured material (40) registered with the red color absorber pattern (16) of multicolor mask (10).

Figs. 8A-8H show a process where three different patterned structures are selectively formed by changing the color of exposing light through the multicolor mask and employing a film 44 curable with panchromatic light. The pan-curable film may be formulated, for example, which contains a polymerizable compound and a mixture of red, green, and blue responsive photoinitiators. When a pan-curable film is used with the present invention, the specific pattern to be formed is selected by adjusting the spectral energy distribution of the exposing light. Therefore, the absorption spectrum of the color absorbing material for the intended pattern should match the wavelength of

exposing light. Figs. 8A-8H also serve to illustrate another embodiment of the present invention. Multicolor mask 10 may optionally have a transparent coating 50 on the top surface. The transparent coating 50 may have insulating, smoothing, planarizing or other properties which improve the performance of the end device 5 that will be formed over the multicolor mask 10. Figs. 8A-8H illustrate the present invention using negative-acting photopatternable materials; one skilled in the art will understand that the present invention may also be used with positive-acting materials. Figs. 8A and 8B show a schematic plan view and cross-sectional view of the multicolor mask (10), which has been coated with a film 10 photopatternable with panchromatic light (44).

Figs. 8C and 8D show a schematic plan view and cross-sectional view of the resulting structure after the film photopatternable with panchromatic light (44) from Fig. 8A has been exposed with blue light and developed, forming a pattern of cured pan- photopatternable material (46) registered with the blue color 15 absorber pattern (14) of multicolor mask (10).

Figs. 8E and 8F show a schematic plan view and cross-sectional view of the resulting structure after the film photopatternable with panchromatic light (44) from Fig. 8A has been exposed with green light and developed, forming a pattern of cured pan-photopatternable material (46) registered with the green 20 color absorber pattern (18) of multicolor mask (10).

Figs. 8G and 8H show a schematic plan view and cross-sectional view of the resulting structure after the film photopatternable with panchromatic light (44) from Fig. 8A has been exposed with red light and developed, forming a pattern of cured pan- photopatternable material (46) registered with the red color 25 absorber pattern (16) of multicolor mask (10). It will be readily understood that combinations of patterns shown in Figs. 8C-8H are possible simply by tuning the color of exposing light (i.e. a blue-plus-green light exposure will cure both shaded regions (46) shown in Fig. 8C and 8E).

An important aspect of this invention is the ability to use one of the 30 color patterns of the multicolor mask to form an aligned pattern of a functional material on at least a portion of the multicolor mask. A number of methods can be

used to cause this patterning. Therefore, both functional materials and photopatternable materials are applied to the multicolor mask and patterned using colored light. General classes of functional materials that can be used include conductors, dielectrics or insulators, and semiconductors. The spectral 5 distribution of illuminating light is modulated by the transmittance of all previously applied and patterned layers. For the purposes of this discussion, the multicolor mask (10) is defined as including all color absorbing portions of the patterned structure with the exception of the photopatternable film. Because the colored light photopatterning process described above and illustrated using Figs. 10 5A-8H results in a change in permeability, solubility, tackiness, mechanical strength, surface reactivity, or index of refraction of the photopatterned material, these properties may be exploited in subsequent fabrication steps. Particularly useful methods to pattern functional and electronic materials using this invention are referred to as liftoff, selective etch, and selective deposition processes.

15 Figs 9A-9F show the operation of this system using a liftoff patterning process. Figs. 9A and 9B show a schematic plan view and cross-sectional view of the multicolor mask (10) with a pattern of photopatterned material (46) registered with green color absorber pattern (18). Referring now to Figs. 9C and 9D, a uniform coating of transparent functional material (48) is 20 applied over the pattern of photopatterned material (46). Figs. 9E and 9F show the final step in a liftoff sequence when the cured material (46) and portions of transparent functional material on top of the cured material are removed. This is accomplished, for example, by treating the sample with a material that selectively attacks the remaining cured material under the functional material. This leaves 25 functional material where there was originally no photopatterned material.

Figs. 10A-10F show the operation of this system embodiment using a selective etch patterning process. Figs. 10A and 10B show a schematic plan view and cross-sectional view of multicolor mask (10) with a uniform coating of transparent functional material (48) under a pattern of cured material (46) 30 registered with green color absorber pattern (18). Figs. 10C and 10D illustrate a subsequent step after the exposed portions of transparent functional material are

removed in an etch process. The sample is exposed to a material that attacks or dissolves the functional layer. Regions of transparent functional material protected by the pattern of cured material (46) are not removed in the etch step. The pattern of transparent functional material (48) is registered with the pattern of 5 cured material (46) and is also registered with green color absorber pattern (18).

Referring now to Figs. 10E and 10F there is illustrated the resulting structure after the pattern of cured material (46) is removed. This may be accomplished, for example, with a compatible solvent or oxygen plasma treatment.

10 Figs. 11A-11F show the operation of this system using a selective deposition patterning process embodiment. A number of deposition processes employing both liquids and vapor phase chemical delivery can be tailored to operate in a manner where material selectively deposits only in certain areas. For example, Figs. 11A and 11B show multicolor mask (10) with a pattern of cured 15 material (46) registered with green color absorber pattern (18). Figs. 11C and 11D illustrate a subsequent step after a transparent functional material (48) is selectively deposited on regions of support (12) that are not covered by the pattern of cured material (46). Referring now to Figs. 11E and 11F a subsequent step is illustrated where the pattern of cured material (46) is removed by treating entire to 20 attack the remaining cured material. The pattern of transparent functional material (48) is registered with the green color absorber pattern (18).

Figs. 12A-14H show a possible sequence of exposure, processing, and deposition steps that would allow construction of a multilayer electronic device as seen in Figs. 14G and 14H.

25 Figs. 12A-12H illustrate one embodiment of the coating and patterning steps for a first transparent layer of an electronic device using a blue photopatternable coating and a selective etch process. Figs. 12A and 12B show multicolor mask (10) coated with a first transparent functional material (20) and a blue photopatternable material (22). This structure is exposed with a light source containing blue light. By way of illustration, the functional material (20) could be 30 a transparent conducting oxide material such as ITO or aluminum doped ZnO.

Because the photopatternable coating (22) drawn in this structure is sensitive only to blue light, the light source may be a white light source, or a colored light source containing blue light.

Referring now to Figs. 12C and 12D, there is illustrated the 5 resulting structure after the exposed blue photopatternable film has been developed, forming a pattern of blue cured material (24) registered with the blue color absorber pattern (14) of multicolor mask (10). Figs. 12E and 12F show an etch step where exposed portions of transparent functional material (20) are removed in, for example, an acid bath, forming a pattern of transparent functional 10 material (26) registered to the blue color absorber pattern (14) of multicolor mask (10). Figs. 12G and 12H show the structure of Fig. 12E after the pattern of blue cured material (24) is removed using, for example, an oxygen plasma treatment.

Figs. 13A-13H illustrate the coating and patterning steps for the second transparent layer of the electronic device using a green curable coating 15 using a selective etch process. Alternatively, the second transparent layer could be patterned be a selective deposition process, a liftoff process, or a light curing process. Figs. 13A and 13B show the multicolor mask (10), including the first patterned transparent layer, coated with a uniform layer of transparent functional material (28) and a green photopatternable layer (30). This structure is exposed 20 with a light source containing green light. By way of example, the transparent functional material (28) could be a dielectric material such as aluminum oxide or alternatively a semiconducting layer such as zinc oxide. This material could be a dielectric or semiconducting layer precursor that is converted in an annealing step to form the electrically functional material. Multiple layers of transparent 25 functional layers could potentially be coated at this step. By way of example, a transparent coating of a dielectric material could be first applied and a second transparent coating of semiconductor material could be subsequently applied. Because the photopatternable coating (30) shown in Figs. 13A and 13B is 30 sensitive only to green light, the light source may be a white light source, or a colored light source containing green light. Figs. 13C and 13D show the resulting structure after the exposed green photopatternable material (30) from Figs. 13A

and 13B has been developed, forming a pattern of green cured material (32) registered with the green color absorber pattern (18) of multicolor mask (10).

Referring now to Figs. 13E and 13F, there is illustrated the structure of Fig. 13C after the exposed portions of transparent functional material 5 (28) are removed in an etch step, forming a pattern of transparent functional material (34) registered to the green color absorber pattern (18) of multicolor mask (10). Figs. 13G and 13H show the structure of Fig. 13E after the pattern of green cured material (32) is removed using, for example, an oxygen plasma treatment.

Figs. 14A-14H illustrate the coating and patterning steps for the 10 third transparent layer of the electronic device using a red curable coating using a selective etch process. Alternatively, the third layer could be patterned with a selective deposition process, a liftoff process, or a light curing process. Figs. 14A and 14B show the multicolor mask (10), including the first and second patterned transparent layers, coated with a uniform layer of transparent functional material 15 (36) and a red-photopatternable material (38). This structure is exposed with a light source containing red light. By way of example, the transparent functional material (36) could be a layer of indium-tin oxide or silver nanoparticles. Because the photopatternable coating (38) drawn in this structure is sensitive only to red light, the light source may be a white light source, or a colored light source 20 containing red light. Figs. 14C and 14D show the resulting structure after the exposed red photopatternable material (38) from Fig. 14A has been developed, forming a pattern of red cured material (40) registered with the red color absorber pattern (16) of multicolor mask (10). Referring now to Figs. 14E and 14F, there is 25 illustrated the structure of Fig. 14C after the exposed portions of transparent functional material (36) are removed in an etch step, forming a pattern of transparent functional material (42) registered to the red color absorber pattern (16) of multicolor mask (10). Figs. 14G and 14H show the structure of Fig 14E after the pattern of red cured material (40) is removed. In this multilayer structure, the pattern of transparent functional material (26) is registered to the blue color 30 absorber pattern (14) of multicolor mask (10). The pattern of transparent functional material (34) is registered to the green color absorber pattern (18) of

multicolor mask (10). The pattern of transparent functional material (42) is registered to the red color absorber pattern (16) of multicolor mask (10).

Figs. 15A and 15B illustrate alternative arrangements of multicolor mask 10 according to the present invention. In these embodiments, multicolor mask 10 is made up of a first mask portion 120 formed on the first side of substrate and a second mask portion 122 formed on the backside of the substrate. This alternative arrangement has the advantage of allowing for the removal of a portion of the multicolor mask. The first mask portion 120 will remain in the final device, while the second mask portion 122 may be removed after completion of the final device. This may be particularly useful in display devices that are viewed through the transparent substrate. The use of these alternative multicolor mask structures should be easily understood with respect to the previous Figures.

Figs. 16 and 16A are analogous to Figs. 14G and 14H and illustrate a completed device formed using a multicolor mask with a first mask portion 120 formed on the first side of substrate and a second mask portion 122 formed on the backside of the substrate. Fig 16B illustrates the completed device after the additional step of removing the second mask portion.

An important aspect of the present invention is the multicolor mask can contain in one structure most or all of the patterning information for the system. This multicolor mask can be generated by any method that produces an image containing the desired colors with sufficient precision and registration for the anticipated application.

The different color absorbers in the multicolored mask may be sequentially or simultaneously deposited and patterned by many methods. One method to produce the multicolor mask is to print the mask using inks containing dyes or pigments with the appropriate spectral qualities. Inks used in the printing could be of any common formulation, which would typically include the colorant material along with a vehicle or solvent, binders, and surfactants. Examples of such multicolor printing systems are inkjet printing, gravure printing, flexography, offset lithography, screen or stencil printing, and relief printing. Color thermographic printing may be used to produce the different color absorbing

layers on the support. Thermochromic compounds, bleachable dyes, heat decomposable compounds, or chemical color formers may be used to form the different color absorbing layer patterns on the support. The different color absorbers may be applied to the support using a laser or thermal transfer process 5 from a donor sheet. Alternately, the color absorbing patterns may be produced on the support by an ablative recording process.

Particularly useful color absorbers are those materials with maximum absorption in a selected portion of the visible band and maximum transmission in remaining portions. So-called block-type dyes and cutoff filter 10 materials are ideal for use in the multicolor mask. The different color absorbers may be applied in any convenient order, or applied in a single layer dispersed in a binder. A receiving layer for color absorbing materials may optionally be coated on the back side of the support before the color absorbing materials are applied.

The different color absorbers in the multicolor mask may be 15 formed by a photolithographic method using, for example, dyed photocurable coatings, such as pigmented or dyed photoresist.

It may be particularly convenient and cost effective to produce a reusable master image for subsequent duplication on the main substrate. In this embodiment, a master mask image is produced of very high accuracy and 20 resolution. This may be accomplished with any of the above techniques. Preferably, this would be done with a photolithographic method that allows a very high quality master image to be produced. It may even be preferable to produce the master image upon a rigid transparent substrate in order to achieve highly accurate vertical alignment between color absorbing layers. The color information 25 in the master color image can be reproduced on the main substrate using a color duplicating or color copying process. For negative-working duplication processes, the master color image would be provided as a negative copy of the multicolor mask.

In a traditional photolithographic process for large area electronic 30 device fabrication, excellent alignment must be achieved over very large areas. In the above method of master duplication, the master may be considerably smaller

and thus easier to fabricate, but then duplicated on the final substrate in a replicating pattern so as to cover a larger area. Although this method of stepping is used for individual mask layers in a conventional photolithographic process, in those processes excellent alignment is still required within the stepping operation.

5 In the current inventive process, considerable tolerance can exist in the location of the individual duplications, since each will contain all the required information for a multilayer pattern.

Color image capture processes employing light sensitive materials may be used to reproduce the master color image. The light sensitive layers can 10 be composed of any set of materials capable of capturing a multicolor light pattern and subsequently being treated or developed in a way to produce a color pattern. Examples of such multicolor image capture materials are color negative photographic imaging layers, color reversal photographic imaging layers, color photothermographic imaging layers, Cycolor® imaging layers, and diffusion 15 transfer color photographic imaging layers such as color instant films, and color Pictrography® film. A master color image may alternatively be reproduced on the main substrate using a color duplicating or copying process such as color electrophotography.

The multicolor mask can be produced on a separate roll of material 20 and then laminated to the substrate. Preferably the lamination is done with the image side of the mask opposite the substrate and that the mask image is as close as possible to the functional layers to be patterned. For embodiments with a portion of the mask on the back side of the substrate, the lamination should be done such that the mask image is as close to the substrate as possible.

25 It may be particularly advantageous for optical considerations to coat the main support layer directly onto the color absorbing layers of the multicolor mask. In this embodiment, the color absorbing layers could be patterned on a carrier support roll and then the main support layer could be cast directly onto the color absorbing layers.

Alternately, the color absorbing layers can be patterned on a separate (donor) roll of material and then all of the color absorbing layers can be transferred in a single step from the donor roll onto the main substrate.

The multicolor mask layers may be separated from the

5 electronically active layers by a barrier layer. Depending on the application, it may be preferable to place the color layers on the back of a thin support so they may be bleached or removed at the end of the fabrication process, and will not create planarity and contamination problems for the active device layers. As noted above, having a portion of the multicolor mask on the device side of the substrate,

10 and a portion on the backside for potential removal is advantageous for some devices. Therefore, it is important to understand the resolution limit for a remotely exposed photoresist layer. This type of exposure is referred to as a proximity exposure in traditional photolithography. In proximity mode, the mask does not contact the wafer, so there are resolution losses due to diffraction effects. A useful

15 discussion of resolution in this so-called proximity printing mode can be found in "Photoreactive Polymers: The Science and Technology of Resists" by A. Reiser, Wiley-Interscience, John Wiley & Sons, 1989, pp. 234-246.

The diffraction effect in proximity printing limits the minimum feature gap on the mask as described by Equation (1):

$$20 \quad W_{\min} \approx \sqrt{k\lambda S} \quad k \approx 1$$

Equation (1)

where  $W_{\min}$  is the minimum feature gap on the mask,  $\lambda$  is the exposure wavelength, and  $S$  is the separation between the mask and the wafer. Similarly,

25 the minimum line/gap period is given by the relationship:

$$2b_{\min} = 3\sqrt{\lambda\left(s + \frac{z}{2}\right)}$$

Equation (2)

where  $b_{\min}$  is the minimum line gap period,  $\lambda$  is the exposure wavelength,  $s$  is the separation between the mask and the wafer, and  $z$  is the resist thickness.

These models indicate that even for a 100  $\mu\text{m}$  distance typical for flexible supports, 6-8  $\mu\text{m}$  features are resolvable, depending on the exposure wavelength. Again at the 100  $\mu\text{m}$  distance, a line/gap periodicity in the range 9-12  $\mu\text{m}$  should be resolvable, depending on the exposure wavelength. In the case of 5 front-side masking, the barrier thickness is also highly tunable. Table A below uses Equations (1) and (2) to predict the minimum feature size and periodicity as a function of the mask and resist separation. Examples using 365 nm or 650 nm exposing light are shown as representative of the two ends of the visible spectrum.

Table A

	Exposing wavelength (nm)	Mask and resist layer separation		
		1 $\mu\text{m}$ separation	10 $\mu\text{m}$ separation	100 $\mu\text{m}$ separation
$W_{\min}$ minimum resolvable gap ( $\mu\text{m}$ )	365	0.6	2	6
	650	0.8	2.5	8
$b_{\min}$ minimum resolvable periodicity ( $\mu\text{m}$ )	365	1.1	3	9
	650	1.5	4	12

10

Based on these models, the multicolor mask can be designed to meet the resolution and transparency requirements of the final device.

Many polymers can be caused to vary their properties by exposure to light, and thus be useful as photopatternable layers. Many typical light sensitive 15 polymers are only sensitive to UV and deep UV radiation. Preferably the photopatternable materials for this invention are rendered sensitive to visible light.

A variety of photopolymerization systems that are activated by visible radiation have been developed. A useful discussion of UV curable and visible light photopatternable materials can be found in "Photoreactive Polymers: 20 The Science and Technology of Resists" by A. Reiser, Wiley-Interscience, John Wiley & Sons, 1989, pp. 102-129. US Patent No. 4,859,572 by Farid et al., cited herein, describes a photographic imaging system, which relies on using visible light to harden an organic component and produce an image pattern. This reference describes a variety of suitable visible light sensitive photoinitiators, 25 monomers, and film formulation guidelines for use in the photopatternable layers of this invention.

Sensitivity to visible light can be accomplished by the use of polymerizable compound along with a photopolymerization initiator. In a preferred embodiment of the invention, the photosensitive resist contains a polymerizable compound selected from among compounds having at least one, 5 preferably two or more, ethylenically unsaturated bond at terminals. Such compounds are well known in the industry and they can be used in the present invention with no particular limitation. Such compounds have, for example, the chemical form of a monomer, a prepolymer, i.e., a dimer, a trimer, and an oligomer or a mixture and a copolymer of them. As examples of monomers and 10 copolymers thereof, unsaturated carboxylic acids (e.g., acrylic acid, methacrylic acid, itaconic acid; crotonic acid, isocrotonic acid, maleic acid, etc.), and esters and amides thereof can be exemplified, and preferably esters of unsaturated carboxylic acids and aliphatic polyhydric alcohol compounds, and amides of unsaturated carboxylic acids and aliphatic polyhydric amine compounds are used. 15 In addition, the addition reaction products of unsaturated carboxylic esters and amides having a nucleophilic substituent such as a hydroxyl group, an amino group and a mercapto group with monofunctional or polyfunctional isocyanates and epoxies, and the dehydration condensation reaction products of these compounds with monofunctional or polyfunctional carboxylic acids are also 20 preferably used. The addition reaction products of unsaturated carboxylic esters and amides having electrophilic substituents such as an isocyanato group and an epoxy group with monofunctional or polyfunctional alcohols, amines and thiols, and the substitution reaction products of unsaturated carboxylic esters and amides having releasable substituents such as a halogen group and a tosyloxy group with 25 monofunctional or polyfunctional alcohols, amines and thiols are also preferably used. As another example, it is also possible to use compounds replaced with unsaturated phosphonic acid, styrene, vinyl ether, etc., in place of the above-unsaturated carboxylic acids.

Specific examples of ester monomers of aliphatic polyhydric 30 alcohol compounds and unsaturated carboxylic acids include, as acrylates, ethylene glycol diacrylate, triethylene glycol diacrylate, 1,3- butanediol diacrylate,

tetramethylene glycol diacrylate, propylene glycol diacrylate, neopentyl glycol diacrylate, trimethylolpropane triacrylate, trimethylolpropane tri(acryloyloxypropyl)ether, trimethylethane triacrylate, hexanediol diacrylate, 1,4-cyclohexanediol diacrylate, tetraethylene glycol diacrylate, pentaerythritol diacrylate, pentaerythritol triacrylate, pentaerythritol tetraacrylate, dipentaerythritol diacrylate, dipentaerythritol hexaacrylate, sorbitol triacrylate, sorbitol tetraacrylate, sorbitol pentaacrylate, sorbitol hexaacrylate, tri(acryloyloxyethyl) isocyanurate, polyester acrylate oligomer, etc. As methacrylates, examples include tetramethylene glycol dimethacrylate, triethylene glycol dimethacrylate, neopentyl glycol dimethacrylate, trimethylolpropane trimethacrylate, trimethylethane trimethacrylate, ethylene glycol dimethacrylate, 1,3- butanediol dimethacrylate, hexanediol dimethacrylate, pentaerythritol dimethacrylate, pentaerythritol trimethacrylate, pentaerythritol tetramethacrylate, dipentaerythritol dimethacrylate, dipentaerythritol hexamethacrylate, sorbitol trimethacrylate, sorbitol tetramethacrylate, and bis[p-(3-methacryloxy-2-hydroxy-propoxy)phenyl]dimethylmethane, bis[p- (methacryloxyethoxy)-phenyl]dimethylmethane. As itaconates, examples include ethylene glycol diitaconate, propylene glycol diitaconate, 1,3-butanediol diitaconate, 1,4-butanediol diitaconate, tetramethylene glycol diitaconate, pentaerythritol diitaconate, and sorbitol tetraitaconate. As crotonates, examples include ethylene glycol dicrotonate, tetramethylene glycol dicrotonate, pentaerythritol dicrotonate, and sorbitol tetradicrotonate. As isocrotonates, examples include ethylene glycol diisocrotonate, pentaerythritol diisocrotonate, and sorbitol tetraisocrotonate. As maleates, examples include ethylene glycol dimaleate, triethylene glycol dimaleate, pentaerythritol dimaleate, and sorbitol tetramaleate. Further, the mixtures of the above-described ester monomers can also be used. Further, specific examples of amide monomers of aliphatic polyhydric amine compounds and unsaturated carboxylic acids include methylenebis acrylamide, methylenebis-methacrylamide, 1,6-hexamethylenebis- acrylamide, 1,6-hexamethylenebis-methacrylamide, diethylenetriaminetris- acrylamide, xylylenebis-acrylamide, and xylylenebis-methacrylamide.

Further, urethane-based addition polymerizable compounds which are obtained by the addition reaction of an isocyanate and a hydroxyl group are also preferably used in the present invention. A specific example is a vinyl urethane compound having two or more polymerizable vinyl groups in one 5 molecule, which is obtained by the addition of a vinyl monomer having a hydroxyl group represented by the following formula (V) to a polyisocyanate compound having two or more isocyanate groups in one molecule.



wherein R and R' each represents H or CH<sub>3</sub>.

10 Other examples include polyfunctional acrylates and methacrylates, such as polyester acrylates, and epoxy acrylates obtained by reacting epoxy resins with (meth)acrylic acids. Moreover, photo-curable monomers and oligomers listed in Sartomer Product Catalog by Sartomer Company Inc. (1999) can be used as well.

15 Depending upon the final design characteristics of the photosensitive material, a suitable addition polymerizable compound or combination of addition polymerizable compounds, having the desired structure and amounts can be used. For example, the conditions are selected from the following viewpoint. For the photosensitive speed, a structure containing many 20 unsaturated groups per molecule is preferred and in many cases bifunctional or more functional groups are preferred. For increasing the strength of an image part, i.e., a cured film, trifunctional or more functional groups are preferred. It is effective to use different functional numbers and different polymerizable groups (e.g., acrylate, methacrylate, styrene compounds, vinyl ether compounds) in 25 combination to control both photosensitivity and strength. Compounds having a large molecular weight or compounds having high hydrophobicity are excellent in photosensitive speed and film strength, but may not be preferred from the point of development speed and precipitation in a developing solution. The selection and usage of the addition polymerizable compound are important factors for 30 compatibility with other components (e.g., a binder polymer, an initiator, a functional material, etc.) in the photopolymerization composition. For example,

sometimes compatibility can be improved by using a low purity compound or two or more compounds in combination. Further, it is also possible to select a compound having specific structure for the purpose of improving the adhesion property of a support, a functional material, and an overcoat layer. Concerning the 5 compounding ratio of the addition polymerizable compound in a photopolymerization composition, the higher the amount, the higher the sensitivity. But, too large an amount sometimes results in disadvantageous phase separation, problems in the manufacturing process due to the stickiness of the photopolymerization composition (e.g., manufacturing failure resulting from the 10 transfer and adhesion of the photosensitive material components), and precipitation from a developing solution. The addition polymerizable compound may be used alone or in combination of two or more. In addition, appropriate structure, compounding ratio and addition amount of the addition polymerizable compound can be arbitrarily selected taking into consideration the degree of 15 polymerization hindrance due to oxygen, resolving power, fogging characteristic, refractive index variation and surface adhesion. Further, the layer constitution and the coating method of undercoating and overcoating can be performed according to circumstances.

Organic polymeric binders which can form a part of the film 20 forming component of the photopatternable layer include: (1) polyesters, including those based on terephthalic, isophthalic, sebacic, adipic, and hexahydroterephthalic acids; (2) nylons or polyamides; (3) cellulose ethers and esters; (4) polyaldehydes; (5) high molecular weight ethylene oxide polymers – e.g., poly(ethylene glycols), having average weight average molecular weights 25 from 4000 to 4,000,000; (6) polyurethanes; (7) polycarbonates; (8) synthetic rubbers – e.g., homopolymers and copolymers of butadienes; and (9) homopolymers and copolymers formed from monomers containing ethylenic unsaturation such as polymerized forms of any of the various ethylenically unsaturated monomers, such as polyalkylenes – e.g. polyethylene and 30 polypropylene; poly(vinyl alcohol); polystyrene; poly(acrylic and methacrylic acids and esters)-e.g. poly(methyl methacrylate) and poly(ethyl acrylate), as well

as copolymer variants. The polymerizable compound and the polymeric binder can be employed together in widely varying proportions, including polymerizable compound ranging from 3-97 percent by weight of the film forming component and polymeric binder ranging from 97-3 percent by weight of the film forming component. A separate polymeric binder, although preferred, is not an essential part of the photopatternable film and is most commonly omitted when the polymerizable compound is itself a polymer.

Various photoinitiators can be selected for use in the above-described imaging systems. Preferred photoinitiators consist of an organic dye.

The amount of organic dye to be used is preferably in the range of from 0.1 to 5% by weight based on the total weight of the photopolymerization composition, preferably from 0.2 to 3% by weight.

The organic dyes for use as photoinitiators in the present invention may be suitably selected from conventionally known compounds having a maximum absorption wavelength falling within a range of 300 to 1000 nm. High sensitivity can be achieved by selecting a desired dye having an absorption spectrum that overlaps with the absorption spectrum of the corresponding color absorbing material of the multicolor mask described above and, optionally, adjusting the absorption spectrum to match the light source to be used. Also, it is possible to suitably select a light source such as blue, green, or red, or infrared LED (light emitting diode), solid state laser, OLED (organic light emitting diode) or laser, or the like for use in image-wise exposure to light.

Specific examples of the photoinitiator organic dyes include 3-ketocoumarin compounds, thiopyrylium salts, naphthothiazolemerocyanine compounds, merocyanine compounds, and merocyanine dyes containing thiobarbituric acid, hemioxanole dyes, and cyanine, hemicyanine, and merocyanine dyes having indolenine nuclei. Other examples of the organic dyes include the dyes described in Chemistry of Functional Dyes (1981, CMC Publishing Co., Ltd., pp. 393-416) and Coloring Materials (60 [4], 212-224, 1987). Specific examples of these organic dyes include cationic methine dyes, cationic carbonium dyes, cationic quinoimine dyes, cationic indoline dyes, and

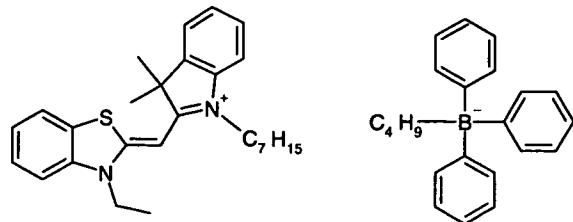
cationic styryl dyes. Examples of the above-mentioned dyes include keto dyes such as coumarin dyes (including ketocoumarin and sulfonocoumarin), merostyryl dyes, oxonol dyes, and hemioxonol dyes; nonketo dyes such as nonketopolymethine dyes, triarylmethane dyes, xanthene dyes, anthracene dyes, 5 rhodamine dyes, acridine dyes, aniline dyes, and azo dyes; nonketopolymethine dyes such as azomethine dyes, cyanine dyes, carbocyanine dyes, dicarbocyanine dyes, tricarbocyanine dyes, hemicyanine dyes, and styryl dyes; quinoneimine dyes such as azine dyes, oxazine dyes, thiazine dyes, quinoline dyes, and thiazole dyes.

Preferably, the photoinitiator organic dye is a cationic dye-borate anion complex formed from a cationic dye and an anionic organic borate. The cationic dye absorbs light having a maximum absorption wavelength falling within a range from 300 to 1000 nm and the anionic borate has four R groups, of which three R groups each represents an aryl group which may have a substitute, and one R group is an alkyl group, or a substituted alkyl group. Such cationic dye-borate anion complexes have been disclosed in US Patent Nos.: 5,112,752; 5,100,755; 5,057,393; 4,865,942; 4,842,980; 4,800,149; 4,772,530; and 15 4,772,541.

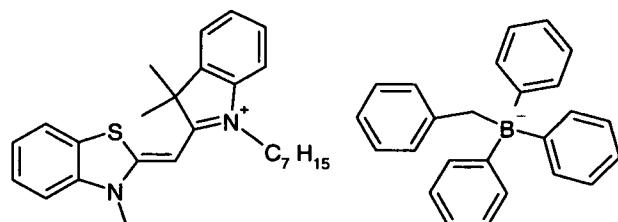
When the cationic dye-borate anion complex is used as the organic dye in the photopolymerization compositions of the invention, it does not require 20 to use the organoborate salt. However, to increase the photopolymerization sensitivity, it is preferred to use an organoborate salt in combination with the cationic dye-borate complex. The organic dye can be used singly or in combination.

Specific examples of the above-mentioned cationic dye-borate salts 25 are given below. However, it should be noted that the present invention is not limited to these examples.

Dye-1

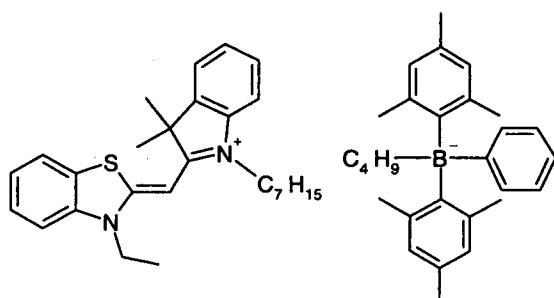


Dye-2



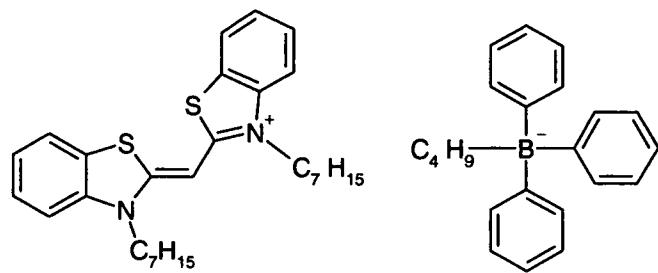
5

Dye-3

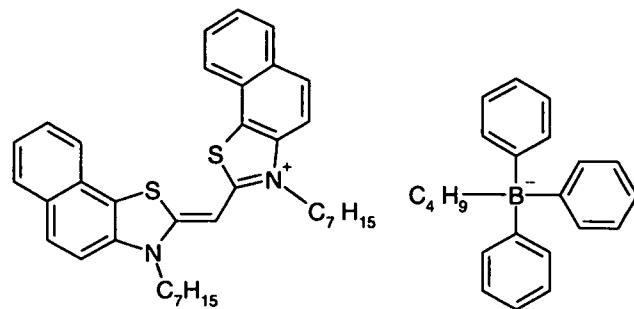


10

Dye-4

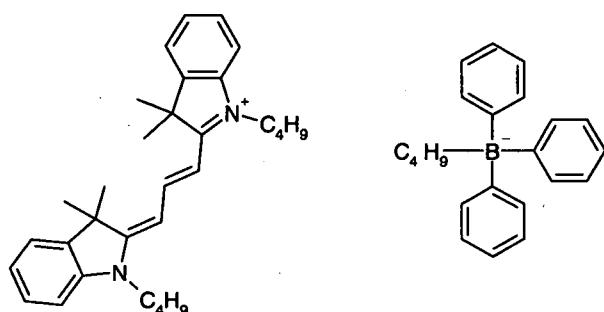


Dye-5

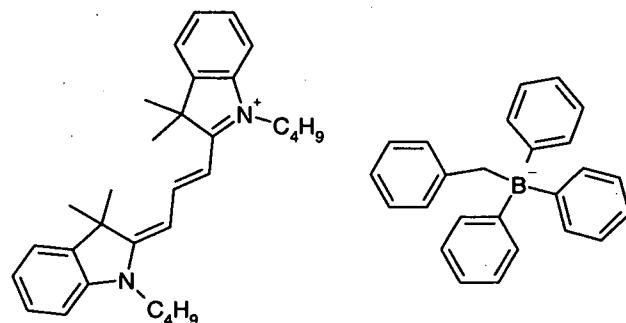


Dye-6

5

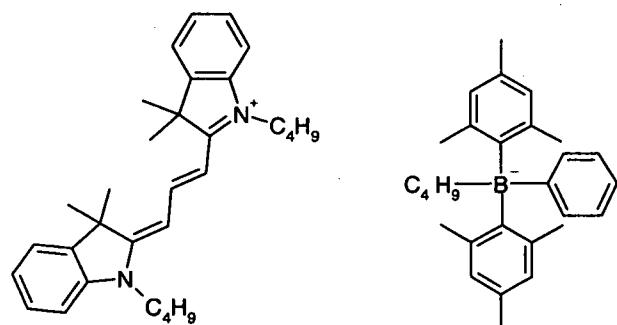


Dye-7

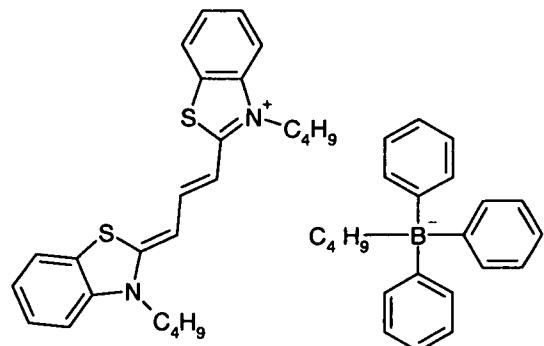


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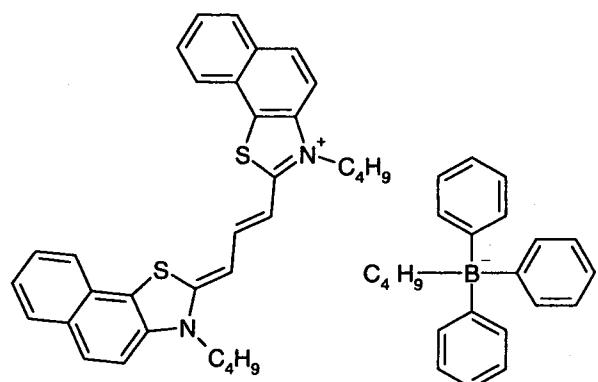
Dye-8



Dye-9

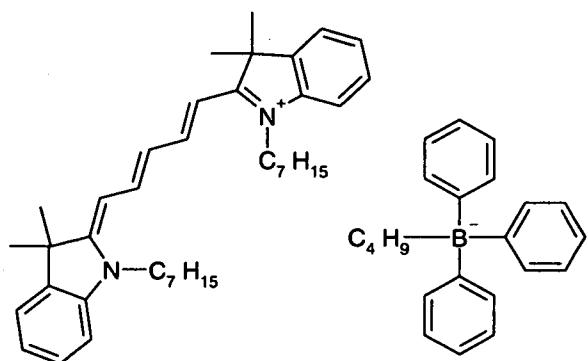


Dye-10

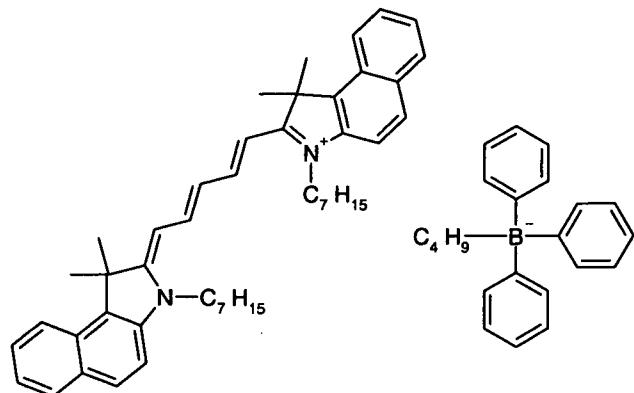


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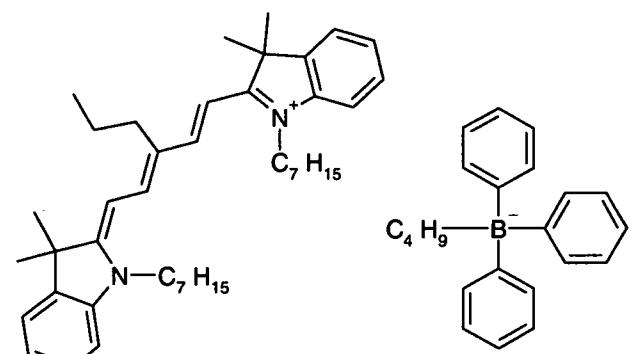
Dye-11



Dye-12

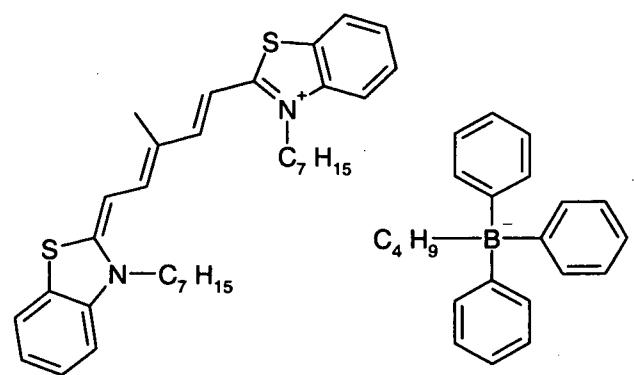


Dye-13

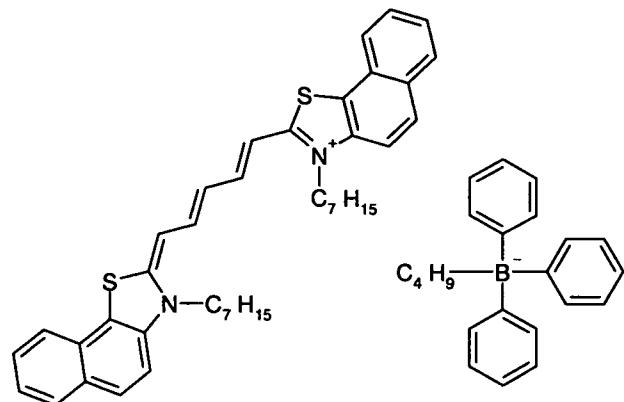


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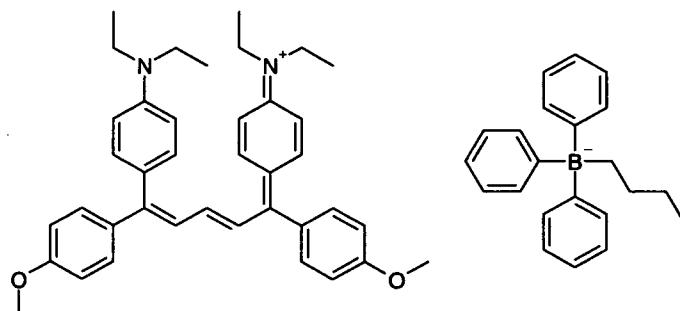
Dye-14



Dye-15

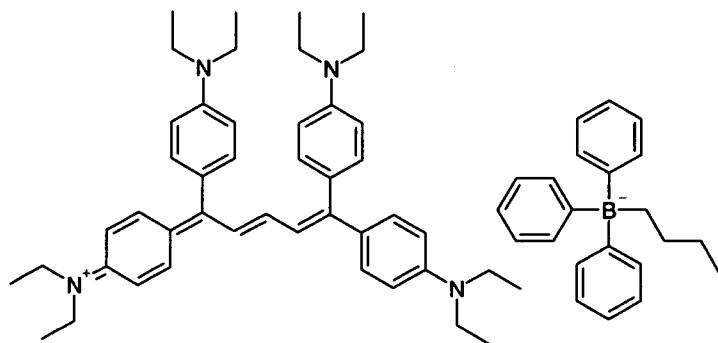


Dye-16



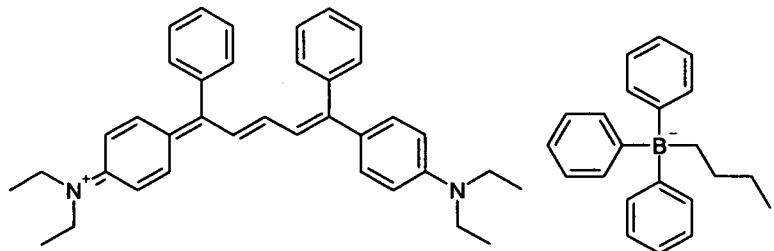
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Dye-17

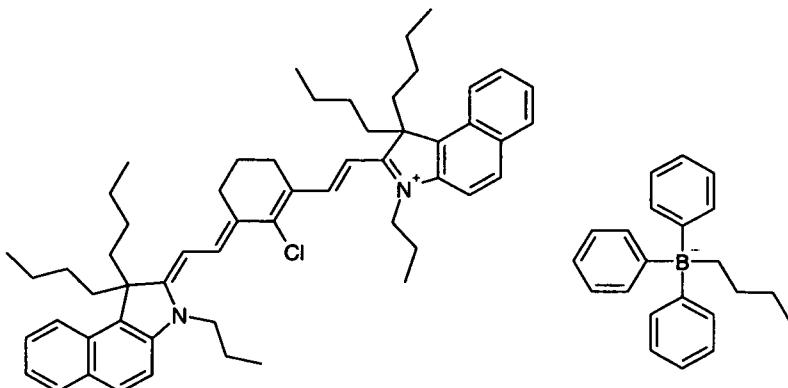


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Dye-18



## Dye-19



It may be preferable to use the photoinitiator in combination with

5 an organic borate salt such as disclosed in US Patent Nos.: 5,112,752; 5,100,755; 5,057,393; 4,865,942; 4,842,980; 4,800,149; 4,772,530; and 4,772,541. If used, the amount of borate compound contained in the photopolymerization composition of the invention is preferably from 0% to 20% by weight based on the total amount of photopolymerization composition. The borate salt useful for the

10 photosensitive composition of the present invention is represented by the following general formula (I).



where Z represents a group capable of forming cation and is not light sensitive,

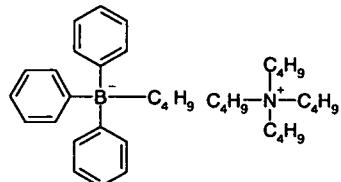
15 and  $[BR_4]^-$  is a borate compound having four R groups which are selected from an alkyl group, a substituted alkyl group, an aryl group, a substituted aryl group, an aralkyl group, a substituted aralkyl group, an alkaryl group, a substituted alkaryl group, an alkenyl group, a substituted alkenyl group, an alkynyl group, a substituted alkynyl group, an alicyclic group, a substituted alicyclic group, a heterocyclic group, a substituted heterocyclic group, and a derivative thereof.

Plural R groups may be the same as or different from each other. In addition, two or more of these groups may join together directly or via a substituent and form a boron-containing heterocycle. Z+ does not absorb light and represents an alkali metal, quaternary ammonium, pyridinium, quinolinium, diazonium,

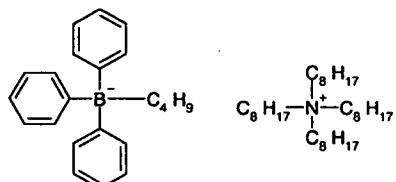
morpholinium, tetrazolium, acridinium, phosphonium, sulfonium, oxosulfonium, iodonium, S, P, Cu, Ag, Hg, Pd, Fe, Co, Sn, Mo, Cr, Ni, As, or Se.

Specific examples of the above-mentioned borate salts are given below. However, it should be noted that the present invention is not limited to 5 these examples.

BS-1

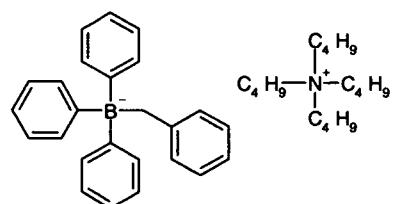


BS-2

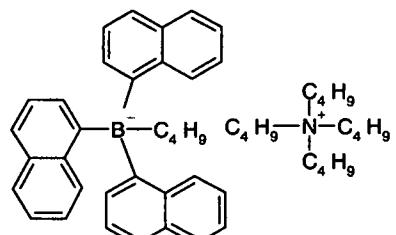


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BS-3

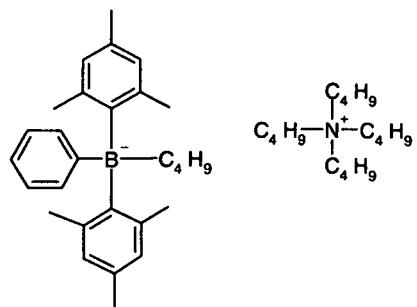


BS-4

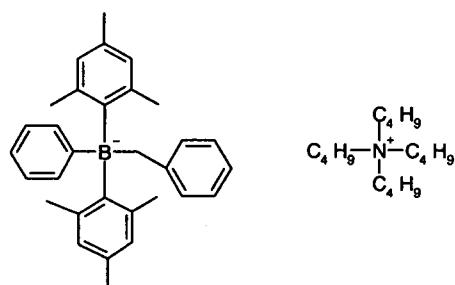


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BS-5

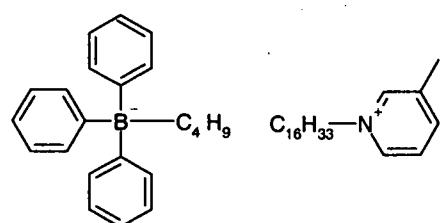


BS-6



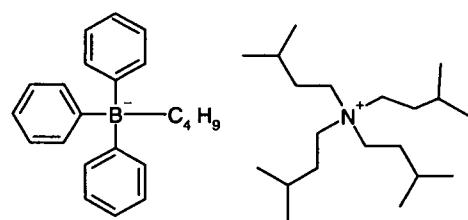
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BS-7

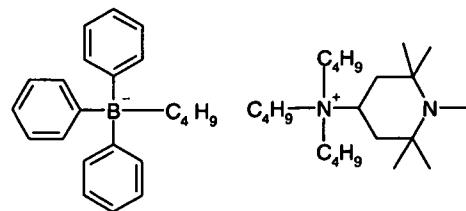


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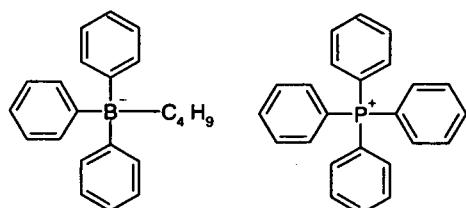
BS-8



BS-9

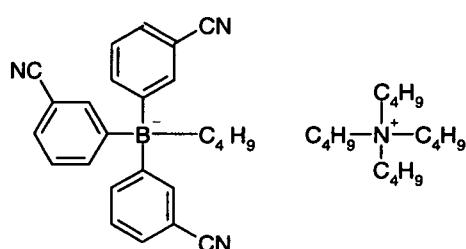


BS-10



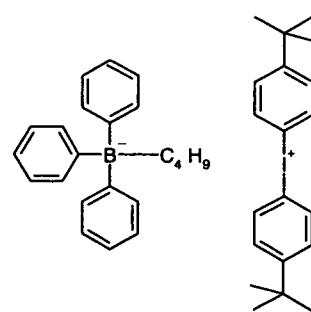
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BS-11

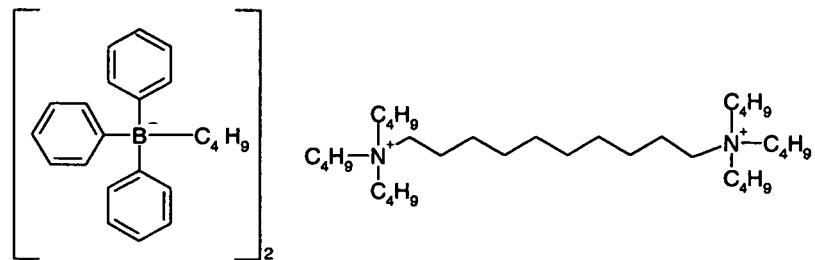


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BS-12

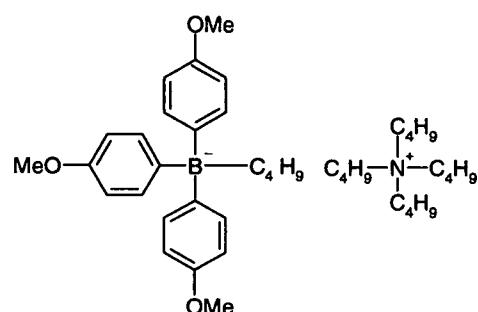


BS-13

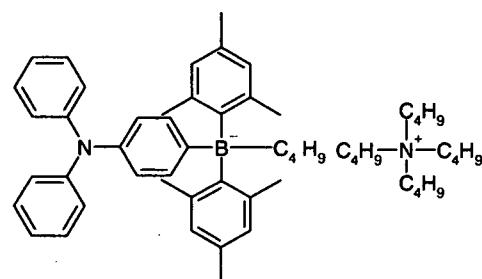


BS-14

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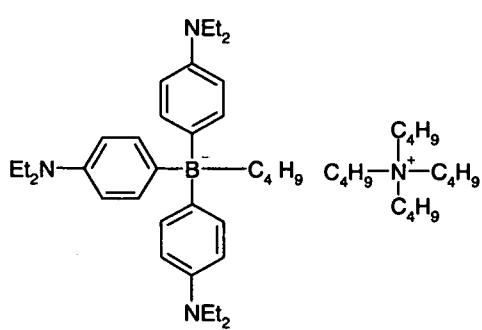


BS-15

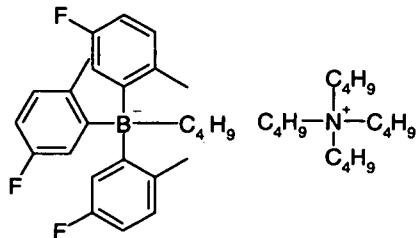


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BS-16



BS-17



Various additives can be used together with the photoinitiator

5 system to affect the polymerization rate. For example, a reducing agent such as an oxygen scavenger or a chain-transfer aid of an active hydrogen donor, or other compound can be used to accelerate the polymerization. An oxygen scavenger is also known as an autoxidizer and is capable of consuming oxygen in a free radical chain process. Examples of useful autoxidizers are N,N- dialkylanilines.

10 Examples of preferred N,N-dialkylanilines are dialkylanilines substituted in one or more of the ortho-, meta-, or para-position by the following groups: methyl, ethyl, isopropyl, t-butyl, 3,4-tetramethylene, phenyl, trifluoromethyl, acetyl, ethoxycarbonyl, carboxy, carboxylate, trimethylsilylmethyl, trimethylsilyl, triethylsilyl, trimethylgermanyl, triethylgermanyl, trimethylstannyl, triethylstannyl,

15 n-butoxy, n-pentyloxy, phenoxy, hydroxy, acetyl-oxy, methylthio, ethylthio, isopropylthio, thio- (mercapto-), acetylthio, fluoro, chloro, bromo and iodo. Representative examples of N,N-dialkylanilines useful in the present invention are 4-cyano-N,N- dimethylaniline, 4-acetyl-N,N-dimethylaniline, 4-bromo-N,N- dimethylaniline, ethyl 4-(N,N-dimethylamino)benzoate, 3-chloro-N,N-

20 dimethylaniline, 4-chloro-N,N- dimethylaniline, 3-ethoxy-N,N-dimethylaniline, 4- fluoro-N,N-dimethylaniline, 4- methyl-N,N-dimethylaniline, 4-ethoxy-N,N- dimethylaniline, N,N-dimethylaniline, N,N-dimethylthioanicidine 4-amino-N,N- dimethylaniline, 3-hydroxy-N,N- dimethylaniline, N,N,N',N'-tetramethyl-1,4- dianiline, 4-acetamido-N,N- dimethylaniline, 2,6-diisopropyl-N,N-dimethylaniline

25 (DIDMA), 2,6-diethyl-N,N- dimethylaniline, N,N, 2,4,6-pentamethylaniline (PMA) and p-t-butyl-N, N- dimethylaniline.

It may be preferable to use the photoinitiator in combination with a disulfide coinitiator. Examples of useful disulfides are described in US Patent No. 5,230,982 by Davis et al.. Two of the most preferred disulfides are mercaptobenzothiazo-2-yl disulfide and 6- ethoxymercaptobenzothiazol-2-yl 5 disulfide.. In addition, thiols, thioketones, trihalomethyl compounds, lophine dimer compounds, iodonium salts, sulfonium salts, azinium salts, organic peroxides, and azides, are examples of compounds useful as polymerization accelerators.

Other additives which can be incorporated into the 10 photopatternable coatings include polymeric binders, fillers, pigments, surfactants, adhesion modifiers, and the like. To facilitate coating on the support and functional layers the photopatternable film composition is usually dispersed in a solvent to create a solution or slurry, and then the liquid is evaporatively removed, usually with heating, after coating. Any solvent can be employed for this purpose 15 which is inert toward the film forming components and addenda of the photopatternable film.

It may be preferable to practice the invention with positive-working photopatternable materials. By way of example, US Patent No. 4,708,925 by Newman (cited herein) describes a positive-working photopatternable composition 20 containing novolak phenolic resins, an onium salt, and a dye sensitizer. In this system, there is an interaction between alkali-soluble phenolic resins and onium salts which results in an alkali solvent resistance when it is cast into a film. Photolytic decomposition of the onium salt restores solubility to the resin. Unlike the quinine diazides which can only be poorly sensitized, if at all, onium salts can 25 be readily sensitized to a wide range of the electromagnetic spectrum from UV to infrared (280 to 1100 nm).

Examples of compounds which are known to sensitize onium salts are those in the following classes: diphenylmethane including substituted diphenylmethane, xanthene, acridine, methine and polymethine (including oxonol, 30 cyanine, and merocyanine) dye, thiazole, thiazine, azine, aminoketone, porphyrin, colored aromatic polycyclic hydrocarbon, p-substituted aminostyryl compound,

aminotriazyl methane, polyarylene, polyarylpolyene, 2,5-diphenylisobenzofuran, 2,5-diarylcylopentadiene, diarylfuran, diarylthiofuran, diarylpyrrole, polyaryl-phenylene, coumarin and polyaryl-2-pyrazoline. The addition of a sensitizer to the system renders it sensitive to any radiation falling within the absorption spectrum 5 of the said sensitizer. Other positive-working systems are known to those skilled in the art.

Once a photopatternable layer is exposed, it can be developed by any means known the art. Development is the process by which the soluble portions of the photopatternable layer are removed. Methods for developing 10 typically include exposure to a selective solvent, heating, or combinations thereof. A liquid developer can be any convenient liquid which is capable of selectively removing the photopatternable layer based on exposure level. The exposed photopatternable layer can be sprayed, flushed, swabbed, soaked, sonicated, or otherwise treated to achieve selective removal. In its simplest form the liquid 15 developer can be the same liquid employed as a solvent in coating the photopatternable film. In some instances the photoresist is not rendered soluble where it is ultimately to be removed, but is instead rendered susceptible to a particular reaction that occurs during exposure to a development solution which then permits solubility.

20 In patterning processes where the photopatterned film is not intended to be part of the final article, it needs to be removed after it has been used to successfully pattern an area. This removal can be accomplished with any means known in the art, included plasma treatments, especially plasmas including oxygen, solvent based stripping, and mechanical or adhesive means.

25 In many embodiments the photopatternable layer is simply a layer used to pattern another functional layer. However, circumstances may exist in which the photopatterned layer is also the functional layer. Examples of this are the use of a photopatternable as a dielectric due to its insulating behavior, or as a structural element such as a small wall or microcell due to its mechanical 30 properties. This use of photopatterned layers as functional layers is not limited to the above examples.

In the process for the article of this invention there is required a light source that emits light of some spectrum, the multicolor mask that contains at least two color records in which each is capable of absorbing light of some spectrum, and a photopatternable layer that is capable of responding to light of some spectrum.

5 The system can function in several modes:

(1) White light, defined as light of a very broad visible spectrum, can be used as the illumination source. In this case, it is required that the photopatternable layer have a sensitivity distribution that substantially matches the 10 absorption spectrum of the target color record of the color mask. Substantially matching spectrum is defined as the integrated product of the two spectra, each normalized to an area of 1, exceeding 0.5, preferably exceeding 0.75, most preferably exceeding 0.9.

(2) Colored light, as defined by light of a narrow spectrum, can be 15 used as the illumination source. In this case, the absorption spectrum of photopatternable layer can be made to substantially match the spectrum of the emitted light, or the absorption spectrum can be broad. The former case may be desirable for improved sensitivity of the photopatternable layer and reduced cross talk between layers, while the latter case may be desirable for allowing several 20 process steps to employ a single photopatternable layer formulation.

In some cases it may be desirable to apply a black layer to part of the multicolor mask. Such a black layer has the property of absorbing substantially all of the light in those areas of the mask having the black layer. If, for example, large areas of the final product are desired to have no patterning, a 25 black printed mask can be used in those areas.

In much of the preceding discussion the color mask is referred to as having color absorption corresponding to the traditional observable colors of the visible spectrum. However, this applies a limitation to the number of individual mask levels that can be accomplished with this approach. In principle a high 30 number of individual color records can be used provided that each color record can be independently addressed in the process. In addition, by utilizing infrared

and ultraviolet portions of the spectrum, the number of mask levels may further be increased. It is envisioned that upwards of 6 individual mask levels can be achieved with the current invention.

In this process, light passes through the multicolor mask and then

5 through the previously applied functional layers on the front of the substrate. As a result, the light must pass through the previously applied layers with weak enough modulation as to not overly affect the resulting images formed on the applied light curable layers. The requirement for transparency of the applied functional layers is thus limited to having an acceptably low effect on the curable layer imaging

10 process. In principle therefore, the previously applied can absorb light uniformly as long as this absorption is low, preferably having an optical density of less than 0.5. Furthermore, the materials can absorb very strongly but only in regions where the imaging chemistry is not being used, or where these spectral ranges have been used but in prior stages of the manufacture of the article. Furthermore, the final

15 layer in the process can be of any opacity, since additional patterning is not required on top.

An aspect of this invention is the ability to at will use one of the colors of the multicolor mask to form a pattern on the front side of the item by the direction light through the substrate to cause an effect. A number of methods can

20 be used to cause the patterning.

(a) A functional material can be coated uniformly over the multicolor mask of the item and then overcoated with a photopatternable resist material that hardens when it is exposed to light through the substrate. The hardened material is then more difficult to remove, so in a subsequent

25 development step, the photopatternable resist is patterned to have openings where no light has struck. The item can then be exposed to a material that attacks the functional layer, thus removing it where no light has struck. This is a negative etch process.

(b) A functional material can be coated uniformly upon over the

30 multicolor mask of the item and then overcoated with a photopatternable resist material that softens when it is exposed to light from the back side. The softened

materials is then easier to remove, so in a subsequent development step, the resist is patterned to have openings where light has struck. The item can then be exposed to a material that attacks the functional layer, thus removing it where light has struck. This is a positive etch process.

5 (c) A photopatternable resist material can be coated followed by exposure and development step as outlined in (a) or (b). This will yield a resist pattern that has holes in it. This can then be overcoated with a uniform layer of a functional material. If the entire item is then treated with a material that attacks the remaining photoresist under the functional material, it can remove material  
10 where photoresist resides. This will leave functional material where there was originally no photoresist.

(d) A number of deposition processes employing both liquids and vapor phase chemical delivery can be tailored to operate in a manner where material selectively deposits only in certain areas. For example, a  
15 photopatternable resist material can be coated followed by exposure and development step as outlined in (a) or (b). Next, a deposition process that leads to material being deposited only in those regions where no resist material remains. The entire item is then treated with a material that attacks the remaining resist. This is selective deposition.

20 A support can be used for supporting the device during manufacturing, testing, and/or use. As used in this disclosure, the terms "support" and "substrate" may be used interchangeably. The skilled artisan will appreciate that a support selected for commercial embodiments may be different from one selected for testing or screening various embodiments. In some embodiments, the  
25 support does not provide any necessary electrical function for the device. This type of support is termed a "non-participating support" in this document. Useful materials can include organic or inorganic materials. For example, the support may comprise inorganic glasses, ceramic foils, polymeric materials, filled polymeric materials, , acrylics, epoxies, polyamides, polycarbonates, polyimides, polyketones, poly(oxy-1,4- phenyleneoxy-1,4-phenylene carbonyl-1,4-phenylene) (sometimes referred to as poly(ether ether ketone) or PEEK), polynorbornenes,

polyphenyleneoxides, poly(ethylene naphthalenedicarboxylate) (PEN), poly(ethylene terephthalate) (PET), poly(ether sulfone) (PES), poly(phenylene sulfide) (PPS), and fiber-reinforced plastics (FRP).

A flexible support is used in some embodiments. This allows for 5 roll-to-roll or roll-to-sheet processing, which may be continuous, providing economy of scale and economy of manufacturing over flat and/or rigid supports. The flexible support chosen preferably is capable of wrapping around the circumference of a cylinder of less than 50 cm diameter, more preferably 25 cm diameter, most preferably 10 cm diameter, without distorting or breaking, using 10 low force as by unaided hands. The preferred flexible support may be rolled upon itself.

If flexibility is not a concern, then the substrate may be a wafer or sheet made of materials including glass as well as any other transparent material.

The thickness of the substrate may vary, and according to particular 15 examples it can range from 10  $\mu\text{m}$  to 1 mm. Preferably, the thickness of the substrate is in the range from 10  $\mu\text{m}$  to 300  $\mu\text{m}$ . Provided the exposing light source is sufficiently collimated to limit the angular spread of light through the support layer, even thicker substrates can be tolerated. Particularly for 20 embodiments where a portion of the multicolor mask is on the back side of the support it may be advantageous, for optical considerations, to coat or cast the main support layer directly onto the color absorbing layers of the second portion of the multicolor mask. In some embodiments, the support is optional, particularly when support layer is a functional layer or a color absorbing layer of the multicolor mask.

25 In addition, the multicolor mask and support may be combined with a temporary support. In such an embodiment, a support may be detachably adhered or mechanically affixed to the multicolor mask.

Any material that can form a film on the substrate can be patterned 30 with this invention, as long as the appropriate etching and or deposition conditions are chosen. Functional materials typically have an inter-related useful function in an electronic component of an electronic device or in electric circuitry. General

classes of functional materials that can be used include conductors, dielectrics or insulators, and semiconductors. Functional materials of the present invention may be deposited in using any convenient method. Typical deposition processes include chemical vapor deposition, sputtering, evaporation, thermal transfer or 5 solution processing. One embodiment of the current invention, the functional materials are applied using gravure or inkjet. In another embodiment the functional material is deposited using Atomic Layer Deposition (ALD). In a preferred embodiment of the present invention, the functional material is deposited by an ALD system consisting of a gas distribution manifold having a 10 plurality of openings through which first and second reactive gases flow as the manifold and the substrate move relative to each other. Co-pending, commonly assigned USSN 11/392,007, filed March 29, 2006, describes such a method in detail.

Conductors can be any useful conductive material. A variety of 15 conductor materials known in the art, are also suitable, including metals, degenerately doped semiconductors, conducting polymers, and printable materials such as carbon ink, silver-epoxy, or sinterable metal nanoparticle suspensions. For example, the conductor may comprise doped silicon, or a metal, such as 20 aluminum, chromium, gold, silver, nickel, copper, tungsten, palladium, platinum, tantalum, and titanium. Conductors can also include transparent conductors such as indium-tin oxide (ITO), ZnO, SnO<sub>2</sub>, or In<sub>2</sub>O<sub>3</sub>. Conductive polymers also can be used, for example polyaniline, poly(3,4-ethylenedioxythiophene)/poly(styrene sulfonate) (PEDOT:PSS). In addition, alloys, combinations, and multilayers of these materials may be most useful.

25 The thickness of the conductor may vary, and according to particular examples it can range from 5 to 1000 nm. The conductor may be introduced into the structure by chemical vapor deposition, sputtering, evaporation and/or doping, or solution processing.

A dielectric electrically insulates various portions of a patterned 30 circuit. A dielectric layer may also be referred to as an insulator or insulating

layer. The dielectric should have a suitable dielectric constant that can vary widely depending on the particular device and circumstance of use. For example, a dielectric constant from 2 to 100 or even higher is known for a gate dielectric. Useful materials for a dielectric may comprise, for example, an inorganic

5 electrically insulating material. Specific examples of materials useful for the gate dielectric include strontiates, tantalates, titanates, zirconates, aluminum oxides, silicon oxides, tantalum oxides, titanium oxides, silicon nitrides, barium titanate, barium strontium titanate, barium zirconate titanate, zinc selenide, and zinc sulfide. In addition, alloys, combinations, and multilayers of these examples can

10 be used as a dielectric. Of these materials, aluminum oxides, silicon oxides, and silicon nitride are useful. The dielectric may comprise a polymeric material, such as polyvinylidenedifluoride (PVDF), cyanocelluloses, polyimides, , polyvinyl alcohol, poly(4-vinylphenol), polystyrene and substituted derivatives thereof, poly(vinyl naphthalene) and substituted derivatives, and poly(methyl

15 methacrylate) and other insulators having a suitable dielectric constant. The gate electric may comprise a plurality of layers of different materials having different dielectric constants.

The thickness of a dielectric layer may vary, and according to particular examples it can range from 15 to 1000 nm. The dielectric layer may be

20 introduced into the structure by techniques such as chemical vapor deposition, sputtering, atomic layer deposition, evaporation, or a solution process.

Semiconductors used in this system may be organic or inorganic. Inorganic semiconductors include classes of materials exhibiting covalently bonded lattices, and may also include amorphous materials where the lattice

25 exhibits only short range order. Examples of useful semiconducting materials are single elements such as silicon or germanium, and compound semiconductors such as gallium arsenide, gallium nitride, cadmium sulfide, and zinc oxide. Useful organic semiconductors include linear acenes such as pentacenes, naphthalenediimides such as those described in co-pending patent applications,

30 perylenediimides, polythiophenes, polyfluorenes.

In typical applications of a thin film transistor, the desire is for a switch that can control the flow of current through the device. As such, it is desired that when the switch is turned on a high current can flow through the device. The extent of current flow is related to the semiconductor charge carrier mobility. When the device is turned off, it is desired that the current flow be very small. This is related to the charge carrier concentration. Furthermore, it is desired that the device be weakly or not at all influenced by visible light. In order for this to be true, the semiconductor band gap must be sufficiently large (> 3 eV) so that exposure to visible light does not cause an inter-band transition. A material that is capable of yielding a high mobility, low carrier concentration, and high band gap is ZnO.

The entire process of making the thin film transistor or electronic device of the present invention, or at least the production of the thin film semiconductor, is preferably carried out below a maximum support temperature of 200° C, more preferably below 150° C, most preferably below 140° C, and even more preferably below 100° C, or even at temperatures around room temperature (25° C to 70° C). The temperature selection generally depends on the support and processing parameters known in the art, once one is armed with the knowledge of the present invention contained herein. These temperatures are well below traditional integrated circuit and semiconductor processing temperatures, which enables the use of any of a variety of relatively inexpensive supports, such as flexible polymeric supports and the multicolor mask. Thus, the invention enables production of relatively inexpensive circuits containing thin film transistors.

Electronically or optically active layers may be formed and doped using solution processes, vacuum vapor deposition techniques, or atmospheric vapor deposition processes such as those described in co-pending Patent Publication Nos. 2007/0228470 and 2007/0238311, both filed March 29, 2006.

The patterning methods of this invention are preferably used to create electrically and optically active components that are integrated on a substrate of choice. Circuit components can comprise transistors, resistors,

capacitors, conductors, inductors, diodes, and any other electronics components that can be constructed by selecting the appropriate patterning and materials. Optically functional components can comprise waveguides, lenses, splitters, diffusers, brightness enhancing films, and other optical circuitry. Structural 5 components can comprise wells, selective patterns of fillers and sealants, patterned barrier layers, walls and spacers.

Electronic devices in which TFTs and other devices are useful include, for example, more complex circuits, e.g., shift registers, integrated circuits, logic circuits, smart cards, memory devices, radio-frequency 10 identification tags, backplanes for active matrix displays, active-matrix displays (e.g. liquid crystal or OLED), solar cells, ring oscillators, and complementary circuits, such as inverter circuits, for example, in which a combination of n-type and p-type transistors are used. In an active matrix displays, a transistor made according to the present invention can be used as part of voltage hold circuitry of a 15 pixel of the display. In such devices, the TFTs are operatively connected by means known in the art.

One example of a microelectronic device is an active-matrix liquid-crystal display (AMLCD). One such device is an optoelectronic display that includes elements having electrodes and an electro-optical material disposed 20 between the electrodes. A connection electrode of the transparent transistor may be connected to an electrode of the display element, while the switching element and the display element overlap one another at least partly. An optoelectronic display element is here understood to be a display element whose optical properties change under the influence of an electrical quantity such as current or 25 voltage such as, for example, an element usually referred to as liquid crystal display (LCD). The presently detailed transistor has sufficient current carrying capacity for switching the display element at such a high frequency that the use of the transistor as a switching element in a liquid crystal display is possible. The display element acts in electrical terms as a capacitor that is charged or discharged 30 by the accompanying transistor. The optoelectronic display device may include many display elements each with its own transistor, for example, arranged in a

matrix. Certain active matrix pixel designs, especially those supplying a display effect that is current driven, may require several transistors and other electrical components in the pixel circuit.

5 The following non-limiting examples further describe the practice of the instant invention.

## EXAMPLES

### A. Visible light curable film components

The following materials and coating solutions were used to prepare the visible light curable films. Stock solution CF-1 contained two grams of 10 polymethylmethacrylate (PMMA) (MW ~75K), 6.5 g of trimethylolpropane triacrylate, and 20 g of anisole. Stock solution CF-2 contained 1.5 grams of ethoxylated trimethylolpropane triacrylate (SR9035 purchased from Sartomer Company, Inc.) and 1.5 g of polyethylene glycol diacrylate (SR610 purchased from Sartomer Company, Inc.) in 4 g of ethanol. Stock solution CF-3 was a 15 commercial resist CT2000L supplied by Fuji Photochemicals containing a methacrylate derivative copolymer and polyfunctional acrylate resin in a mixture of 2-propanol-1-methoxyacetate and 1-ethoxy-2-propanol acetate. Stock solution CF-4 contained 1.25 g of a Novolak resin, and 0.2 g of Irgacure 250 (purchased from CIBA Specialty Chemicals), in MEK. Stock solution CF-5 was a positive- 20 working commercial resist SC-1827, (purchased from Rohm and Haas Electronic Materials). Stock solution CF-6 was prepared as follows. DEHESIVE 944 is a vinyl-terminated dimethylsiloxane polymer supplied by Wacker Chemie AG. Crosslinker V24 is a methylhydrogenpolysiloxane supplied by Wacker. Catalyst OL is an organoplatinum complex in polydimethylsiloxane, also supplied by 25 Wacker. Crosslinker V24 and Catalyst OL are used for additional curing of vinyl-terminated siloxane polymers such as DEHESIVE 944. A solution was prepared which contained 3.3 g of a 1% solution of polymethylmethacrylate dissolved in toluene, 0.5 g of a 10% solution of TMPTA in toluene, 0.25 g of a 0.1% solution of Photoinitiator A in anisole, 0.5 g of a solution containing 1.08% DEHESIVE 30 944, 0.002% Crosslinker V24, and 0.06% Catalyst OL in a mixture of 33 parts

toluene and 48 parts heptane, and 0.85 g of toluene. One gram of the resulting solution was diluted with 5 g of toluene to prepare stock solution CF-6.

The stock solutions CF1-CF4 were sensitized to visible light by addition of a dye photoinitiator. Photoinitiator structures appear in Table 1.

5 Photoinitiator solutions were prepared as follows. YPI-1 was a 1% solution of yellow photoinitiator A in anisole. YPI-2 was a 1% solution of yellow photoinitiator A in ethanol. YPI-3 was a 1% solution of yellow photoinitiator A in cyclohexanone. MPI-1 was a 1% solution of magenta photoinitiator B in anisole. MPI-2 was a 1% solution of magenta photoinitiator B in ethanol. MPI-3 was a 1%  
10 solution of magenta photoinitiator in cyclohexanone. CPI-1 was a 1% solution of cyan photoinitiator C in anisole. CPI-2 was a 1% solution of photoinitiator C in ethanol. CPI-3 was a 1% solution of photoinitiator C in cyclohexanone.

Developer solution D-1 was MIBK. Developer solution D-2 was ethanol. Developer solution D-3 was an aqueous solution containing 0.002 M

15 tetramethylammonium hydroxide and 0.002 M diethanolamine. Developer solution D-4 was Kodak Goldstar Plus Positive Plate Developer. Developer solution D-5 was Microposit<sup>TM</sup> MF<sup>TM</sup>-319, purchased from Rohm and Haas Electronic Materials

**Table 1**

	Dye	$\lambda_{max}$
Photoinitiator A		450 nm
Photoinitiator B		555 nm
Photoinitiator C		645 nm

20

### **B. Electronic materials deposition and patterning**

The following materials and methods were used to deposit electronic materials. Alumina coatings were of type A-1 were applied using a

CVD process with trimethylaluminum and water as reactive materials entrained in a nitrogen carrier gas. Zinc oxide coatings of type ZnO-1 were applied using a CVD process with diethyl zinc and water as reactive materials entrained in a nitrogen carrier gas. The device used to prepare the  $Al_2O_3$  layers of type A-2 and 5 A-3 and ZnO layers of type ZnO-2 has been described in detail in US Patent Application No. 11/627,525. Alumina coatings of type A-2 were applied using this coating device with trimethylaluminum and water as reactive materials entrained in a nitrogen carrier gas. Alumina coatings of type A-3 were applied using this coating device with dimethylaluminum isopropoxide (DMAI) and water 10 as reactive materials. Zinc oxide coatings of type ZnO-2 were applied using this ALD coating device with diethyl zinc and water as reactive materials entrained in a nitrogen carrier gas. Indium tin oxide (ITO) coatings were applied using a sputter coater. Aluminum coatings (Al) were evaporated.

The following solutions were used to etch the functional materials.

15 E-1 was a 50/50 mixture of HCl and water. E-2 was Kodak Ektacolor RA-4 bleach-fix solution. E-3 was a 0.25 molar solution of acetic acid in water. E-4 was Microposit<sup>TM</sup> MF<sup>TM</sup>-319 Developer purchased from Rohm and Haas Electronic Materials. Subbing layer S-1 was a 7.5% solution of polycyanoacrylate in a 50/50 mixture of acetonitrile and cyclopentanone. S-2 was Omnicat<sup>TM</sup>, 20 purchased from MicroChem.

**Example 1: Multicolor mask formed by direct printing process**

In this example, a multicolor mask MM-1 was prepared containing 3 color absorbing layers, with each color corresponding to an individual functional layer of an array of thin film transistor devices. A color image was created using 25 Photoshop 6.0. In this image, the blue channel contained the gate layer design as a blue color absorber pattern BCA-1. The green channel contained the semiconductor layer design as a green color absorber pattern GCA-1. The red channel contained the source and drain design as a red color absorber pattern RCA-1. This color image was printed onto a transparent support using a Kodak 30 Professional 8670 Thermal Printer loaded with Kodak Professional Ektatherm

XLS transparency media. The Optical Density (Status M) to red light (cyan OD), green (magenta OD), and blue light (yellow OD) and peak wavelength of the individual color absorbing layers in MM-1 is shown in Table 2 below.

**Table 2**

	Optical Density (Status M)			$\lambda_{\max}$
	Cyan OD	Magenta (OD)	Yellow (OD)	
BCA-1	0.02	0.08	1.38	460 nm
GCA-1	0.08	1.44	0.38	548 nm
RCA-1	1.73	0.29	0.09	683 nm

5

**Example 2: Multicolor mask formed by photolithography process**

In this example, a multicolor mask MM-2 was prepared containing 3 color absorbing layers RCA-2, GCA-2, and BCA-2 and planarizing layer P-2, with each color corresponding to an individual functional layer of an array of thin

10 film transistor devices. Cyan (SC3200L), magenta (SM3000L), yellow (SY3000L), and clear (CT-2000L) UV curable photoresists were purchased from Fujifilm Electronic Materials Co., Ltd. Laser-written molybdenum on glass masks were prepared for the gate layer (CG-1), semiconductor and dielectric layers (CG-2), and source and drain layers (CG-3) of the array of thin film transistor devices.

15 Photoresist coatings were aligned and exposed to UV light using a contact aligner equipped with a 200W Mercury-Xenon lamp. Red color absorbing layer RCA-2 was applied to a clean glass support by the following method. The glass substrate was spin coated (at 1000 RPM) with the cyan photoresist SC3200L, baked for 1 minute at 95° C, and exposed using mask CG-1. The coating was developed, and

20 baked for 5 minutes at 200° C, forming red color absorbing layer RCA-2. The sample was then spin coated (at 1000 RPM) the magenta photoresist SM3000L, baked for 1 minute at 95° C, and exposed using mask CG-3. The coating was developed, and baked for 5 minutes at 200° C forming green color absorbing layer GCA-2. The sample was then spin coated (at 1000 RPM) with yellow photoresist,

25 SY3000L, baked for 1 minute at 95° C, and exposed using mask CG-2 (contact exposure). The yellow photoresist layer was developed, and baked for 5 minutes at 200° C forming blue color absorbing layer BCA-2. The sample was then spin coated (at 1000 RPM) with clear photoresist CT2000L, exposed to UV light and

baked for 5 minutes at 200° C. The resulting multicolor mask MM-2 contained an array of registered cyan (RCA-2), magenta (GCA-2), and yellow (BCA-2) patterns and a clear planarizing layer P-2. The Optical Density (Status M) to red light (cyan OD), green (magenta OD), and blue light (yellow OD) and peak wavelength 5 of the individual color absorbing layers in MM-2 is shown in Table 3 below.

**Table 3**

	Optical Density (Status M)			
	Cyan OD	Magenta (OD)	Yellow (OD)	$\lambda_{max}$
BCA-2	0.03	0.05	0.97	465 nm
GCA-2	0.05	1.02	0.18	565 nm
RCA-2	0.94	0.13	0.05	625 nm

**Example 3: Photographic replication of a master color image**

This example illustrates the replication of a master color mask 10 using a full color, high resolution, silver halide film to form multicolor masks MM-3. A multicolor mask was prepared in the same manner as described in Example 2. Twenty copies of the multicolor mask were prepared by contact printing to Eastman Color Print™ film using a photographic enlarger. The exposed photographic negatives were developed, fixed, and washed. Each 15 resulting multicolor mask MM-3 contained an array of registered cyan, magenta, and yellow patterns.

**Example C4-C6:**

In this set of examples, multicolor mask MM-1 is used in combination with blue-sensitive coating C-4, green-sensitive coating C-5, and red-sensitive coating C-6, to produce distinct photopatterns. Because the colorants in the multicolor mask are spectrally distinct, the patterns encoded in the multicolor 20 masks are addressed simply by changing the dye photoinitiator and color of exposing light.

Photosensitive coatings were prepared from a solution that 25 contained 3.9 g of CF-1 and 0.5 g of the photoinitiator solution indicated in Table 4. The coatings were prepared by spin coating at 1000 RPM for one minute and were dried for one minute at 80° C and loaded in a glass cell purged with nitrogen. The peak wavelength of the resulting photosensitive coatings,  $\lambda_{max}$ , is shown in Table 4. The coatings were illuminated with colored light in such fashion that

exposing light passed through the glass support and multicolor mask MM-1 before reaching the photosensitive coating. Unexposed portions of the photosensitive coating were removed by developing for 1 minute in D-1. These steps resulted in formation of a negative patterned polymer film corresponding to a specific a color pattern on the multicolor mask. Results are summarized in Table 4 below. In example C-4, the photopattern produced corresponded to the blue color absorber pattern BCA-1, establishing that this coating formulation is a negative-working, blue sensitive film. In example C-5, the photopattern produced corresponded to the green color absorber pattern GCA-1, establishing that this coating is a negative-working, green sensitive film. In example C-6, the photopattern produced corresponded to the red color absorber pattern RCA-1, establishing that this formulation is a negative-working, red sensitive film.

**Table 4**

Example	Stock Solution	Photoinitiator	$\lambda_{\text{max}}$	Exposing light	Photopattern obtained
C-4	CF-1	YPI-1	450 nm	Blue	BCA-1 / negative
C-5	CF-1	MPI-1	557 nm	Green	GCA-1 / negative
C-6	CF-1	CPI-1	656 nm	Red	RCA-1 / negative

**15 Example C7-C9:**

In this set of examples, multicolor mask MM-2 is used in combination with blue-sensitive coating C-7, green-sensitive coating C-8, and red-sensitive coating C-9, to produce distinct photopatterns. These photosensitive coatings are negative-working.

20 Coating solutions contained 7 g of CF-2 and 0.6 g of the photoinitiator solution indicated in Table 5. These solutions were coated, exposed, and developed in the same manner as for examples C4-C6, with the exception that multicolor mask MM-2 was used and the coatings were developed using developer solution D-2. These steps resulted in formation of a negative patterned polymer film corresponding to a specific a color pattern on the multicolor mask. Results are summarized in Table 5 below. In example C-7, the photopattern produced corresponded to the blue color absorber pattern BCA-2, establishing that this coating formulation is a negative-working, blue sensitive

film. In example C-8, the photopattern produced corresponded to the green color absorber pattern GCA-2, establishing that this coating is a negative-working, green sensitive film. In example C-9, the photopattern produced corresponded to the red color absorber pattern RCA-2, establishing that this formulation is a negative-working, red sensitive film.

**Table 5**

Example	Stock Solution	Photoinitiator	Exposing light	Photopattern obtained
C-7	CF-2	YPI-2	Blue	BCA-2 / negative
C-8	CF-2	MPI-2	Green	GCA-2 / negative
C-9	CF-2	CPI-2	Red	RCA-2 / negative

**Examples C10-C12:**

In this set of examples, multicolor mask MM-2 is used in combination with blue-sensitive coating C-10, green-sensitive coating C-11, and red-sensitive coating C-12, to produce distinct photopatterns. These photosensitive coatings are negative-working.

Coating solutions contained 4 g of CF-3 and 0.5 g of the photoinitiator solution indicated in Table 6. The coating solution was spin coated at 2000 RPM for one minute and dried for 2 minutes at 90° C. A 10% PVA coating was applied at 1000 RPM for 2 minutes and dried at 90° C for 2 minutes at 90° C. These coatings were exposed in air and developed in the same manner as for examples C7-C9, with the exception that multicolor mask MM-2 was used and the coatings were developed using developer solution D-3. These steps resulted in formation of a negative patterned polymer film corresponding to a specific a color pattern on the multicolor mask. Results are summarized in Table 6 below. In example C-10, the photopattern produced corresponded to the blue color absorber pattern BCA-2, establishing that this coating formulation is a negative-working, blue sensitive film. In example C-11, the photopattern produced corresponded to the green color absorber pattern GCA-2, establishing that this coating is a negative-working, green sensitive film. In example C-12, the photopattern produced corresponded to the red color absorber pattern RCA-2, establishing that this formulation is a negative-working, red sensitive film.

**Table 6**

Example	Stock Solution	Photoinitiator	Exposing light	Photopattern obtained
C-10	CF-3	YPI-3	Blue	BCA-2 / negative
C-11	CF-3	MPI-3	Green	GCA-2 / negative
C-12	CF-3	CPI-3	Red	RCA-2 / negative

**Examples C13-C15**

In this set of examples, multicolor mask MM-2 is used in combination with blue-sensitive coating C-13, green-sensitive coating C-14, and red-sensitive coating C-15, to produce distinct photopatterns. These photosensitive coatings are positive-working.

Coating solution CF13 contained 5 g of CF-4 and 2 g of the YPI-3.

Coating solution CF-14 contained 5 g of CF-4 and 2 g of MPI-3. These coating solutions were spin coated at 2000 RPM for one minute and dried for 1 minute at 80° C. These coatings were exposed in air and developed in the same manner as for examples C4-C6, with the exception that multicolor mask MM-2 was used and the coatings were developed for 20 seconds using developer solution D-4. These steps resulted in formation of a positive patterned polymer film corresponding to a specific a color pattern on the multicolor mask. Results are summarized in Table 7 below. In example C-13, the photopattern produced corresponded to the blue color absorber pattern BCA-2, establishing that this coating formulation is a positive-working, blue sensitive film. In example C-14, the photopattern produced corresponded to the green color absorber pattern GCA-2, establishing that this coating is a positive-working, green sensitive film. In example C-15, the photopattern produced corresponded to the red color absorber pattern RCA-2, establishing that this formulation is a positive-working, red sensitive film. Similarly, coating C-16 was prepared and exposed with blue light, developed using D-5, forming a positive resist image corresponding to BCA-2.

**Table 7**

Example	Stock Solution	Photoinitiator	Exposing light	Photopattern obtained
C-13	CF-4	YPI-3	Blue	BCA-2 / positive
C-14	CF-4	MPI-3	Green	GCA-2 / positive
C-16	CF-5	As purchased	Blue	BCA-2 / positive

**Example C17-C34: Materials patterning using etch process**

In Examples C17-C34, a multicolor mask is used in combination with visible-light sensitive coatings to pattern transparent electronic materials in an etch process. Because the colorants in the multicolor mask are spectrally distinct, the patterns encoded in the multicolor masks are addressed simply by changing the dye photoinitiator and color of exposing light.

Photosensitive coatings were prepared directly on the transparent functional material, exposed, and developed according to the procedures described for Examples C4-C16, as indicated in Table 8. Coatings were exposed in such fashion that exposing light passed through the support and multicolor mask before reaching the photosensitive coating. The functional material was patterned by immersing the sample in the etch bath indicated, rinsed, and dried. Results are summarized in Table 8. For Examples C-17 through C-30, a negative-working resist pattern is combined with an etch step. This sequence of steps results in a functional material pattern which corresponds to a negative of the color absorber pattern. For Examples C31-C35, a positive-working resist pattern is combined with an etch step. This sequence of steps results in a functional material pattern which corresponds to a positive of the color absorber pattern. The results in Table 8 further illustrate that a single multicolor mask may be used to produce a variety of functional material patterns by varying the sensitivity of the photopatternable material.

**Table 8**

Example	Functional Material	Photopatternable Formulation	Exposing light	Etch Bath	Photopattern obtained
C-17	ITO	C-4	Blue	E-1	BCA-1 / negative
C-18	ITO	C-5	Green	E-1	GCA-1 / negative
C-19	ITO	C-6	Red	E-1	RCA-1 / negative
C-20	ITO	C-7	Blue	E-1	BCA-2 / negative
C-21	ITO	C-11	Green	E-1	GCA-3 / negative
C-22	ITO	C-12	Red	E-1	RCA-2 / negative
C-23	ITO	C-13	Blue	E-1	BCA-2 / positive
C-24	ITO	C-16	Blue	E-1	BCA-2 / positive
C-25	Ag	C-6	Red	E-2	RCA-1 / negative
C-26	ZnO	C-4	Blue	E-3	BCA-1 / negative
C-27	ZnO	C-5	Green	E-3	GCA-1 / negative
C-28	ZnO	C-6	Red	E-3	RCA-1 / negative
C-29	ZnO	C-7	Blue	E-3	BCA-2 / negative
C-30	ZnO	C-11	Green	E-3	GCA-2 / negative
C-31	ZnO	C-16	Blue	E-3	BCA-2 / positive
C-32	Al <sub>2</sub> O <sub>3</sub>	C-13	Blue	E-4	BCA-2 / positive
C-33	Al <sub>2</sub> O <sub>3</sub>	C-16	Blue	E-4	BCA-2 / positive
C-34	Al <sub>2</sub> O <sub>3</sub>	C-16	Blue	E-4	BCA-3 / positive

**Examples C35-C40: Materials patterning using liftoff process**

In Examples C35-C40, a multicolor mask is used in combination with visible-light sensitive coatings to pattern transparent electronic materials in a liftoff process. Because the colorants in the multicolor mask are spectrally distinct, the patterns encoded in the multicolor masks are addressed simply by changing the dye photoinitiator and color of exposing light.

A subbing layer was applied to the substrates as indicated in Table 9 to improve the quality of the patterned layers. Photosensitive coatings were prepared, exposed, and developed according to the procedures described for Examples C4-C16, as indicated in Table 9. Coatings were exposed in such fashion that exposing light passed through the support and multicolor mask before reaching the photosensitive coating. The functional material was deposited on the substrate after the photosensitive coating was developed. The photopatterned material was removed from the substrate using acetone. Results are summarized in Table 9. For Examples C-35 through C-38, a negative-working resist pattern is combined with an liftoff step. This sequence of steps results in a functional material pattern which corresponds to a positive of the color absorber pattern. For Examples C38-C39, a positive-working resist pattern is combined with a liftoff step. This sequence of steps results in a functional material pattern which

corresponds to a negative of the color absorber pattern. The results in Table 9 further illustrate that a single multicolor mask may be used to produce a variety of functional material patterns by varying the sensitivity of the photopatternable material.

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**Table 9**

Example	Functional Material	Photopatternable Formulation	Exposing light	Sub	Liftoff Solvent	Photopattern obtained
C-35	Ag	C-7	Blue	S-1	acetone	BCA-1 / positive
C-36	Al <sub>2</sub> O <sub>3</sub> /ZnO stack	C-7	Blue	S-1	Acetone	BCA-2 / positive
C-37	Al <sub>2</sub> O <sub>3</sub>	C-7	Blue	S-1	Acetone	BCA-2 / positive
C-38	Al <sub>2</sub> O <sub>3</sub>	C-11	Green	Omnicoat	Acetone	GCA-2 / positive
C-39	Al <sub>2</sub> O <sub>3</sub>	C-16	Blue	Omnicoat	Acetone	BCA-2 / negative

#### **Examples C40-C42: Materials patterning using selective deposition process**

In Examples C40-C42, a multicolor mask is used in combination with visible-light sensitive coatings to pattern transparent electronic materials in a 10 selective deposition process. Because the colorants in the multicolor mask are spectrally distinct, the patterns encoded in the multicolor masks are addressed simply by changing the dye photoinitiator and color of exposing light.

Photosensitive coatings were prepared, exposed, and developed according to the procedures described for Examples C4-C16, as indicated in Table 15 10. Coatings were exposed in such fashion that exposing light passed through the support and multicolor mask before reaching the photosensitive coating. After the photosensitive coating was developed, the functional material was selectively deposited on regions not masked by the photopatterned coating. Results are summarized in Table 10. For example C40, a layer of silver nanoparticle ink was 20 selectively applied using an inkjet printing device, the sample was annealed to form a conducting patterned film. Inkjet printing experiments were performed using a system consisting of a sample platen supported by a set of X-Y translation stages, piezoelectric demand-mode printheads supported by a Z translation stage, and software to control these components. The printheads of this inkjet system are 25 suited to dispense droplets in the 20-60 picoliter range. Approximately 2 cc of the

silver nanoparticle ink was placed in a sample cartridge which was then screwed to the printing fixture. The printhead was primed with ink using pressurized nitrogen. The sample was placed on the sample holder of the inkjet printing system, and the silver nanoparticle ink was selectively applied in the desired 5 pattern, aligned to the photopatterned film with the aid of a top view camera. Optical micrographs clearly showed the silver pattern was corresponded to the green color absorbing pattern, without “spillage” onto the top surface of the photopatterned coating C-7. For example C-41, a 200 Angstrom thick ZnO film of type ZnO-2 was selectively grown on the photopatterned coating of type C10. 10 Ellipsometry data indicated the ZnO was selectively deposited. For example C-42, stock solution CF-6 was spin coated at 2000 RPM, baked at 80 C for one minute, exposed and developed using developer D-1. An Al<sub>2</sub>O<sub>3</sub> layers of type A-3 was selectively deposited. Ellipsometry data indicated the photosensitive layer inhibited a 500 Angstrom thick layer of alumina.

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**Table 10**

Example	Functional Material	Functional Material Deposition Method	Photopatternable Formulation	Exposing light	Material pattern obtained
C-40	Ag	Inkjet	C-7	Green	GCA-2 / positive
C-41	ZnO-2	ALD	C-10	Blue	BCA-2 / positive
C-42	Al <sub>2</sub> O <sub>3</sub> - 3	ALD	CF-6	Blue	BCA-2 / positive

**Example T-43: Thin Film Transistor**

In this example, thin film transistors were prepared using a multicolor mask to pattern transparent electronic materials. A multicolor mask 20 was prepared on a glass substrate and a planarizing layer was applied. The thin film transistors were prepared on the same side of the substrate as the color mask. Electrical characterization of the fabricated devices was performed with a Hewlett Packard HP 4156® parameter analyzer. Device testing was done in air in a dark enclosure.

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The results were averaged from several devices. For each device, the drain current (Id) was measured as a function of source-drain voltage (Vd) for various values of gate voltage (Vg). Furthermore, for each device the drain

current was measured as a function of gate voltage for various values of source-drain voltage. Vg was swept from minus 10 V to 40 V for each of the drain voltages measured, typically 5 V, 20 V, and 35 V, and 50 V. Mobility measurements were taken from the 35V sweep.

5 Parameters extracted from the data include field-effect mobility ( $\mu$ ), threshold voltage ( $V_{th}$ ), subthreshold slope (S), and the ratio of  $I_{on}/I_{off}$  for the measured drain current. The field-effect mobility was extracted in the saturation region, where  $V_d > V_g - V_{th}$ . In this region, the drain current is given by the equation (see Sze in *Semiconductor Devices—Physics and Technology*, John 10 Wiley & Sons (1981)):

$$I_d = \frac{W}{2L} \mu C_{ox} (V_g - V_{th})^2$$

Where, W and L are the channel width and length, respectively, and  $C_{ox}$  is the capacitance of the oxide layer, which is a function of oxide thickness and dielectric constant of the material. Given this equation, the saturation field-effect 15 mobility was extracted from a straight-line fit to the linear portion of the  $\sqrt{I_d}$  versus  $V_g$  curve. The threshold voltage,  $V_{th}$ , is the x-intercept of this straight-line fit.

The first step in fabricating the transistors was to prepare the multicolor mask using the same procedure employed to fabricate multicolor mask 20 MM-2. In this color mask, the cyan color absorber pattern was a negative of the desired TFT gate pattern. The blue color absorber pattern was a positive of the desired TFT gate dielectric and semiconductor pattern. The green color absorber was a negative of the desired TFT source/drain/bussing pattern. The sample was coated with 1000 Angstroms of sputtered indium-tin-oxide. The ITO gate was 25 patterned using red-sensitive photosensitive material, employing the coating, exposing, develop, and etch process procedure described for Example C-22. Residual photosensitive material was removed from the sample in an acetone bath and an oxygen plasma treatment. The sample was then coated with 1000 Angstroms of aluminum oxide A-2 applied using an atmospheric pressure 30 deposition process. The aluminum oxide dielectric material was patterned using

blue-sensitive photosensitive material, employing the coating, exposing, develop, and etch process described for Example C-33. Residual photosensitive material was removed from the sample in an acetone bath and an oxygen plasma treatment. The sample was coated with 1000 Angstroms of sputtered indium-tin-oxide. The 5 ITO source, drain, and bussing structure was patterned using green-sensitive photosensitive material, employing the coating, exposing, develop, and etch process procedure described for Example C-21. Residual photosensitive material was removed from the sample in an acetone bath and an oxygen plasma treatment. The zinc oxide semiconductor material was patterned using a blue-sensitive 10 photocrosslinkable material in a selective deposition process. The same coating, exposing, develop, and ZnO deposition process was used as was described for Example 41. Devices were then tested for transistor activity. The transistors prepared using the multicolor mask yielded a mobility of  $0.3 \text{ cm}^2/\text{V}\cdot\text{s}$ .

The fabrication sequence employing a multicolor mask as outlined 15 above allows for accurate placement of any number of transparent functional layers on the substrate even while exposing the substrate to varying temperature and solvent treatments. Further, even for large area substrates, there are no issues with dimensional distortion of the substrate or mechanical alignment errors leading to cumulative and catastrophic alignment errors. Use of the multicolor 20 mask and visible light curable films provides a unique solution to the registration challenge without the need for expensive alignment equipment and processes.

**CLAIMS:**

1. A process for forming a structure comprising:
  - a) providing a transparent support;
  - b) forming a multicolor mask having at least a first color pattern and a second color pattern, wherein at least the first color pattern is on a first side of the transparent support; and
  - c) forming at least two layers of patterned functional materials, a first and second layer of patterned functional material, each formed by:
    - i) coating a layer of a photopatternable material sensitive to visible light on the first side of the support after forming the multicolor mask;
    - ii) exposing the layer of photopatternable material through the multicolor mask with visible light to form a photopattern corresponding to one of the first color pattern and second color pattern of the multicolor mask wherein the photopattern is composed of photopatternable material in a second exposed state that is different from a first as-coated state;
    - iii) depositing a layer of a functional material before or after coating the layer of photopatternable material; and
    - iv) patterning the layer of functional material using the photopattern such that the resulting patterned functional material corresponds to said one of the first color pattern and second color pattern; and
2. The process of claim 1 further comprising the step of coating a transparent layer over the first color pattern prior to coating a layer of photopatternable material over the first color pattern.

3. The process of claim 1 wherein the second color pattern is on the side opposite the first side of the transparent support.

4. The process of claim 1 wherein the second color pattern is 5 on the first side of the transparent support and is either in a same layer or in a different layer as the first color pattern.

5. The process of claim 1 wherein the light utilized for exposing the layer of photopatternable material has a spectrum matching one of 10 the colors of the multicolored mask.

6. The process of claim 1 wherein the visible light utilized for exposing the layer of photopatternable material comprises white light, and the photopatternable layer is only sensitive to light having a spectrum matching one of 15 the colors of the multicolored mask.

7. The process of claim 1 wherein said multicolored mask comprises a multicolor layer formed by photographic replication of a master color image onto said transparent support.

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8. The process of claim 1 wherein said multicolored mask is laminated onto said transparent support after being preformed on a substrate separate from said structure.

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9. The process of claim 1 wherein said multicolored mask comprises at least two colors selected from magenta, cyan, and yellow.

10. The process of claim 1 wherein said multicolored mask is directly printed onto said transparent support.

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11. The process of claim 1 wherein said transparent support comprises glass or a flexible polymer sheet.

12. The process of claim 1 wherein the photopatternable  
5 material is sensitive to a single color of the multicolor mask.

13. The process of claim 12 wherein the photopatternable layer  
contains an initiator system for ethylenic addition containing, as a photoinitiator, a  
dye capable of absorbing imaging radiation to achieve an excited state only within  
10 a specific color wavelength range.

14. The process of claim 1 wherein, in further steps, the  
transparent support on the side opposite to said multicolored mask is coated with a  
material curable by ultraviolet light, and said material is exposed through an  
15 ultraviolet masking layer.

15. The process of claim 1 wherein said photopatternable  
material curable by visible light contains at least one addition-polymerizable  
ethylenically unsaturated compound selected from the group consisting of  
20 monomers, oligomers, crosslinkable polymers, and mixtures thereof, having a  
boiling point above 100 degrees C at atmospheric pressure.

16. The process of claim 1 wherein said at least two layers of  
patterned functional materials comprises dielectric, conductive, or semiconductive  
25 material.

17. An article comprising a transparent support, a multicolor  
mask having at least two colored patterns on the support and at least two layers of  
patterned functional material on the same side of the support as at least one  
30 colored pattern and in register with the at least one colored pattern.

18. The article of claim 17 wherein at least one of said at least two layers of patterned functional material is conductive, dielectric, or semiconductive.

5 19. The article of claim 17 wherein said article comprises on the same side of the transparent support as the at least one colored pattern, in order, as said at least two layers of patterned functional material, a patterned conductive layer and a patterned dielectric layer.

10 20. The article of claim 17 wherein said article comprises on the same side of the transparent support as the at least one colored pattern, in order, as said at least two layers of patterned functional material, either

(a) a patterned conductive layer, a patterned dielectric layer, a patterned semiconductive layer, and a patterned conductive layer; or

15 (b) a patterned conductive layer, a patterned dielectric layer, a patterned conductive layer, and a patterned semiconductive layer.

21. The article of claim 17 wherein all layers of patterned functional materials on the same side of the transparent support as the at least one colored pattern are transparent or wherein a layer of patterned functional material furthest from the transparent support is not transparent.

22. The article of claim 17 wherein said at least two layers of patterned functional materials comprises, respectively, two or more materials selected from the following:

(a) a dielectric material selected from a group consisting of aluminum oxide, silicon oxide, silicon nitrides and mixtures thereof;

30 (b) a conductive material selected from the group consisting of transparent conductors such as indium-tin oxide (ITO), ZnO, SnO<sub>2</sub>, or In<sub>2</sub>O<sub>3</sub>, metals, degenerately doped semiconductors, conducting polymers, carbon ink, silver-epoxy, sinterable metal nanoparticle suspensions, and mixtures thereof; and

(c) a semiconductive material selected from the group consisting of zinc oxide, tin oxide, and mixtures thereof.

23. The article of claim 17 wherein said article comprises a  
5 transistor.

24. The article of claim 17 wherein the multicolor mask comprises an imaging layer comprising a photographic layer or a dye-receiving layer

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25. A process for forming a structure comprising:  
a) providing a transparent support;  
b) forming a multicolor mask having at least a first color pattern and a second color pattern, wherein at least the first color pattern is on a first side 15 of the transparent support;  
c) coating a layer of a first photopatternable material sensitive to visible light on the first side of the support after forming the multicolor mask;  
d) exposing the layer of photopatternable material through the multicolor mask with visible light to form a first pattern corresponding to the first 20 color pattern wherein the first pattern is composed of photopatternable material in a second exposed state that is different from a first as-coated state;  
e) depositing a layer of a first functional material before or after coating the first photopatternable material;  
f) patterning the layer of a first functional material using the first 25 pattern such that the layer of a first functional material has a pattern corresponding to the first color pattern;  
g) coating a layer of a second photopatternable material sensitive to visible light on the first side of the support after forming the multicolor mask;  
h) exposing the layer of a second photopatternable material 30 through the multicolor mask with visible light to form a second pattern corresponding to the second color pattern wherein the second pattern is composed

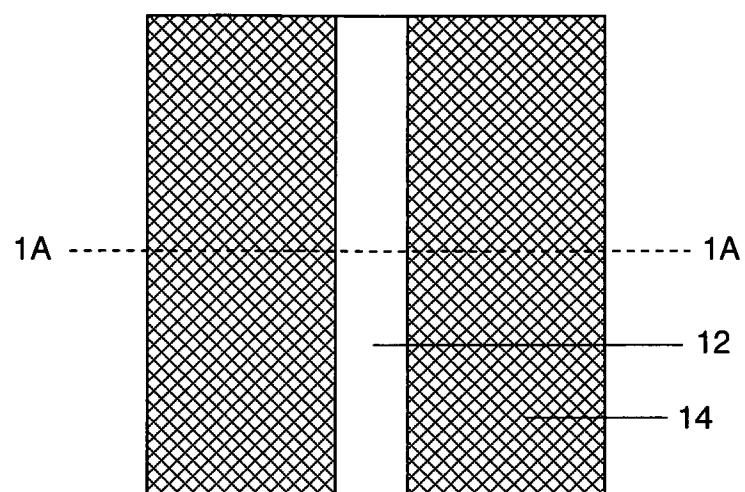
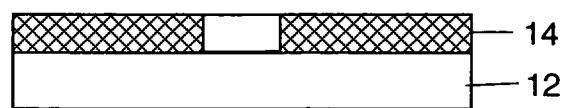
of the second photopatternable material in a second exposed state that is different from a first as-coated state;

i) depositing a layer of a second functional material before or after coating the second photopatternable material; and

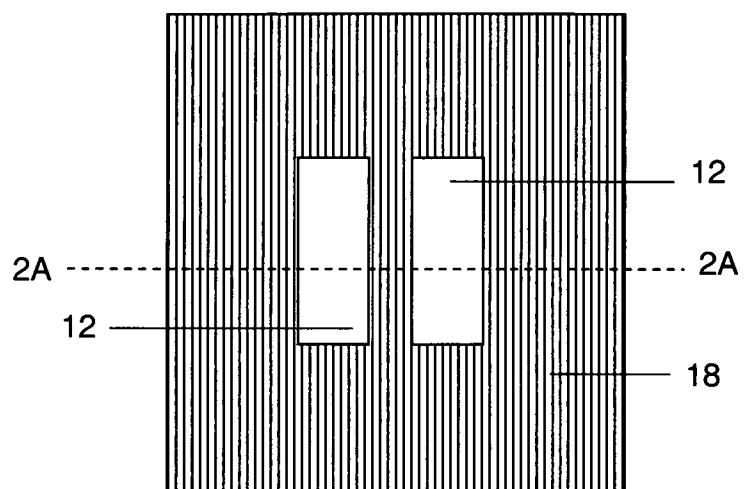
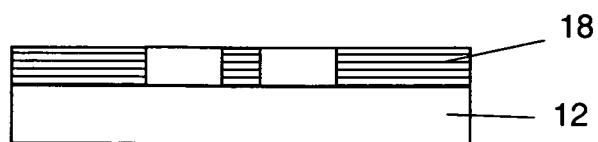
5 j) patterning the layer of a second functional material using the second pattern such that the layer of a second functional material has a pattern corresponding to the second color pattern;

wherein at least the first color pattern, support, and patterned first and second functional materials remain in the structure.

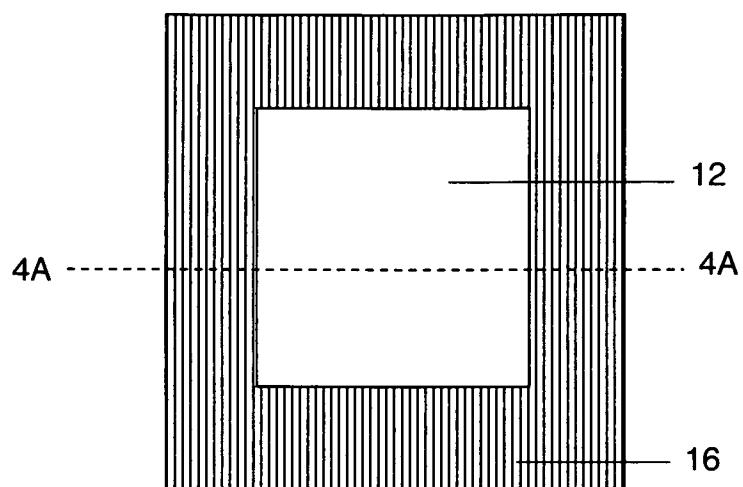
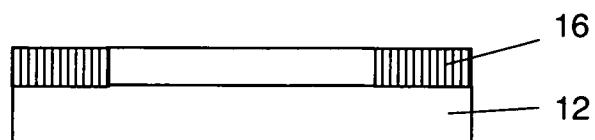
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**FIG. 1****FIG. 1A**

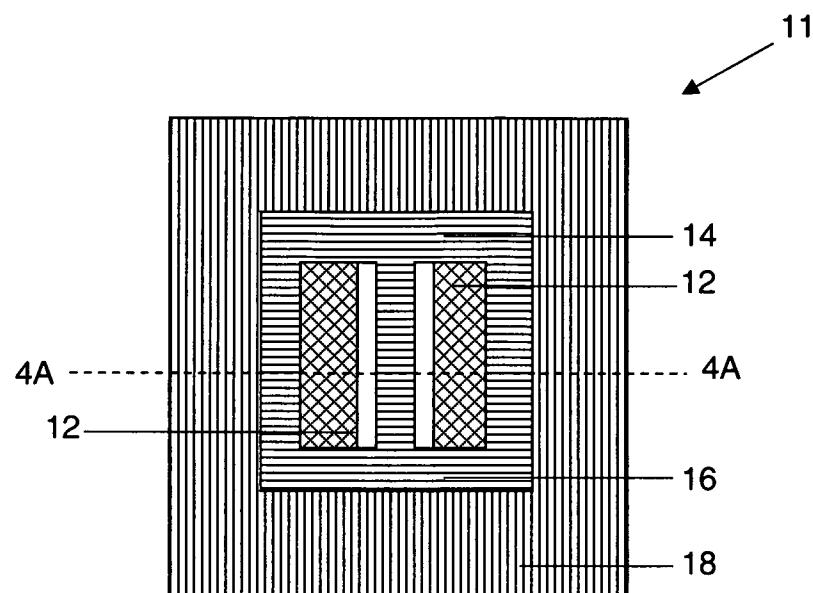
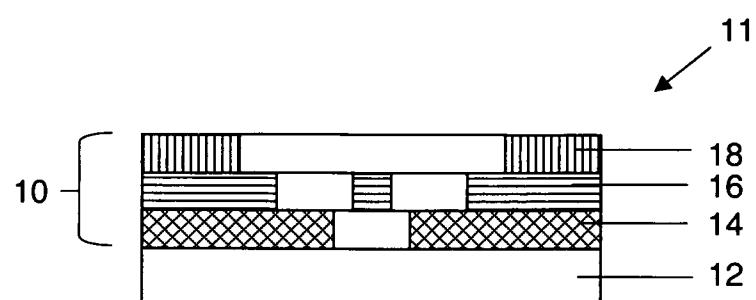
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**FIG. 2****FIG. 2A**

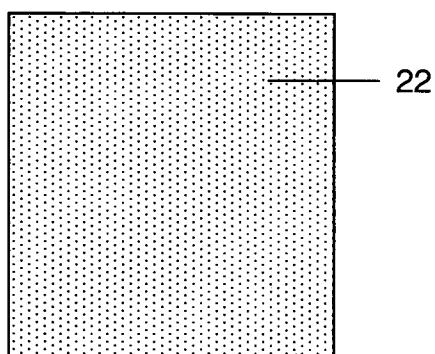
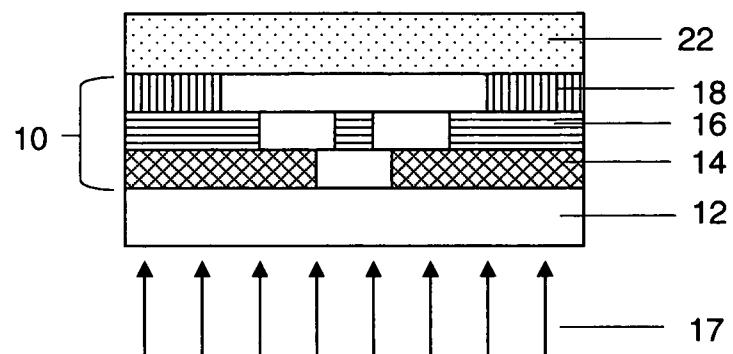
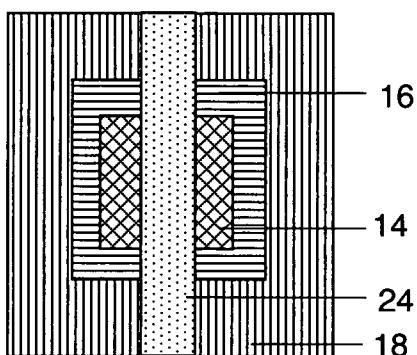
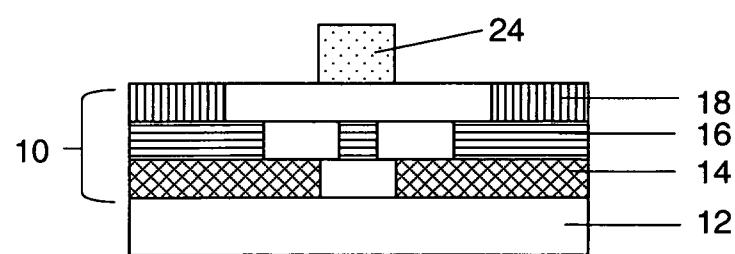
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***FIG. 3******FIG. 3A***

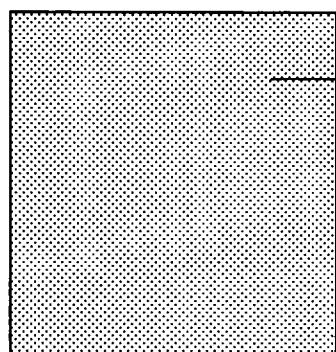
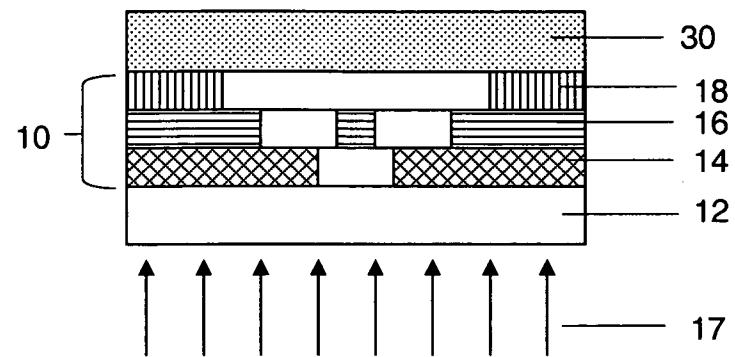
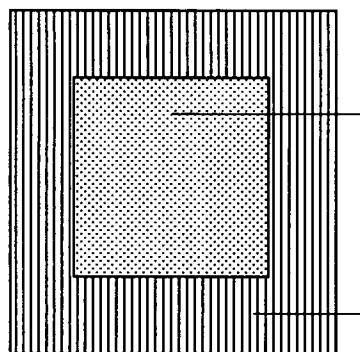
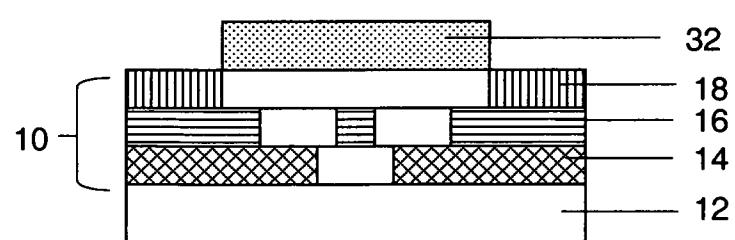
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**FIG. 4****FIG. 4A**

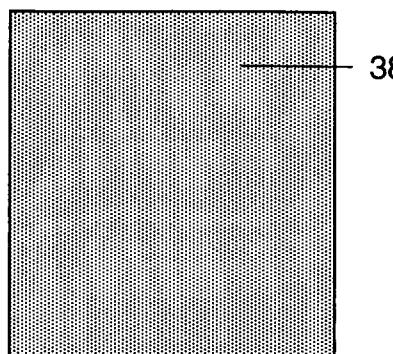
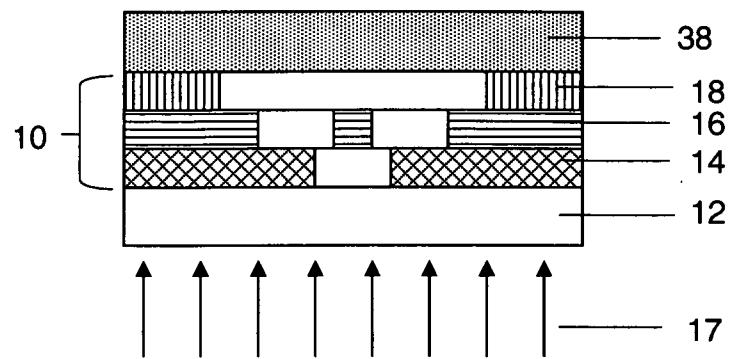
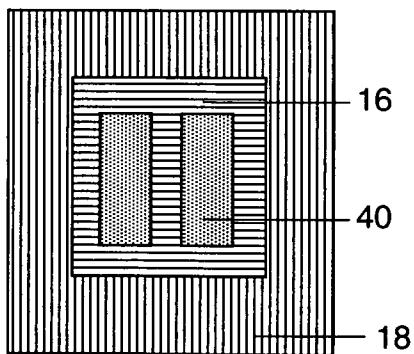
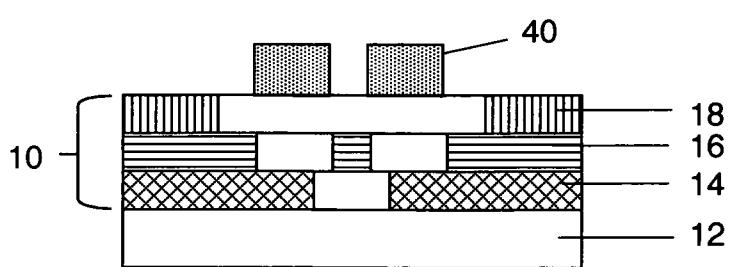
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**FIG. 5A****FIG. 5B****FIG. 5C****FIG. 5D**

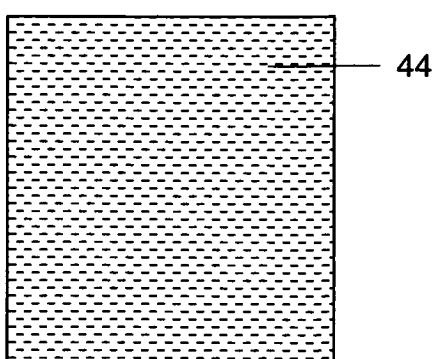
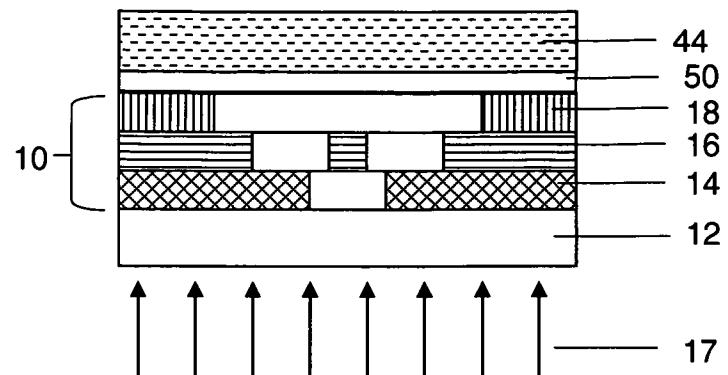
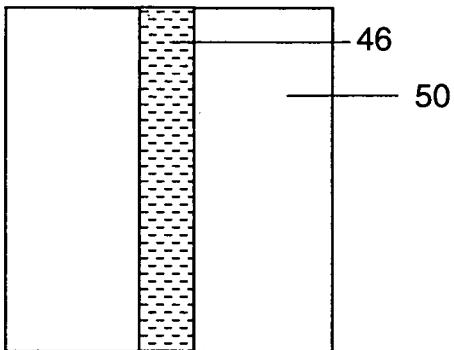
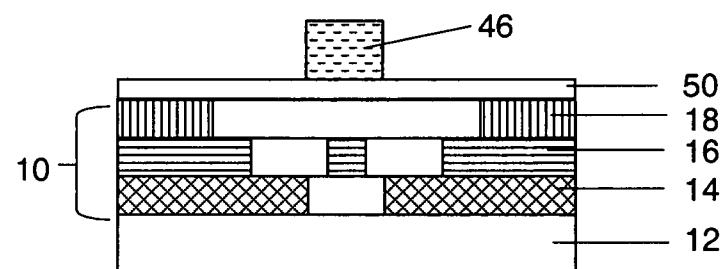
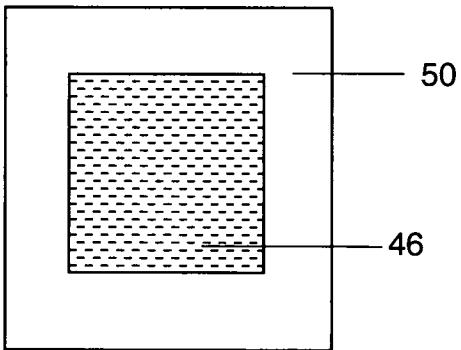
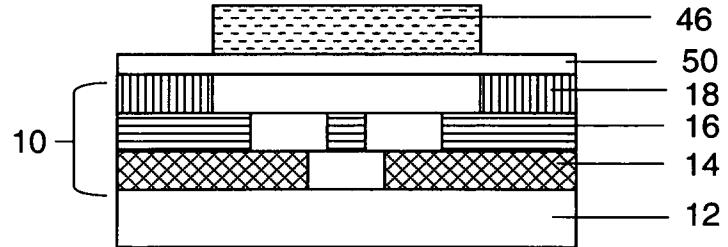
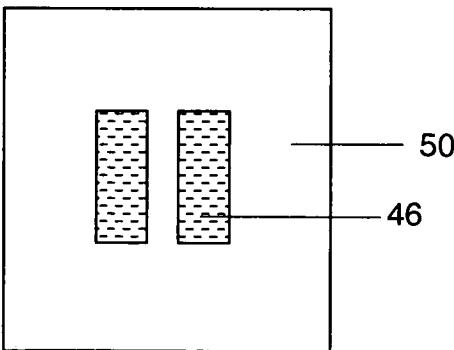
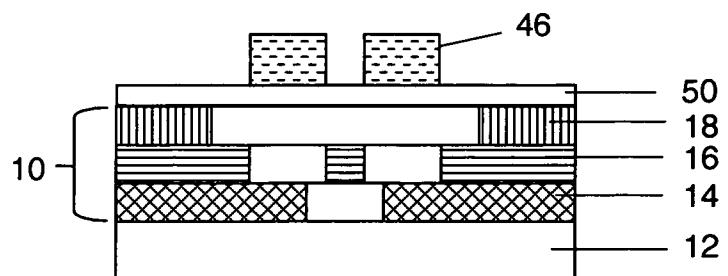
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**FIG. 6A****FIG. 6B****FIG. 6C****FIG. 6D**

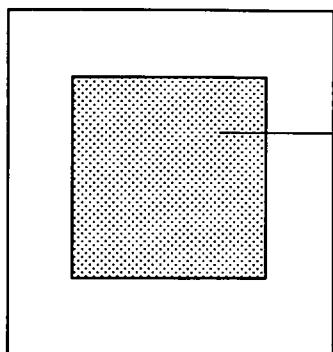
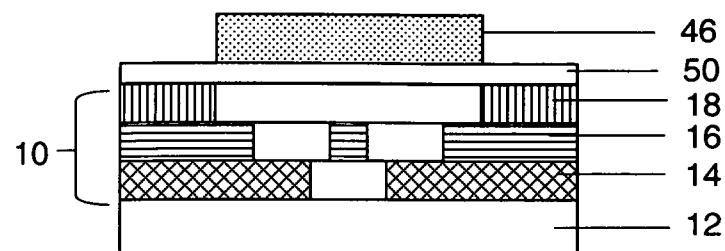
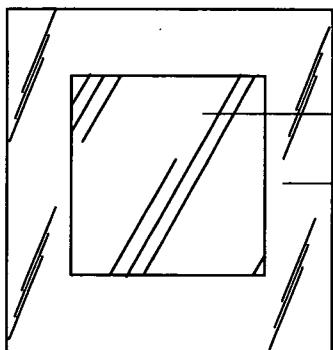
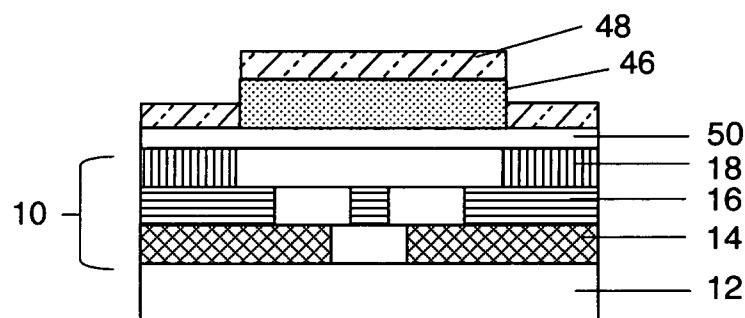
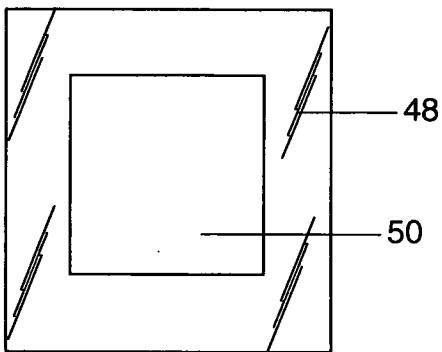
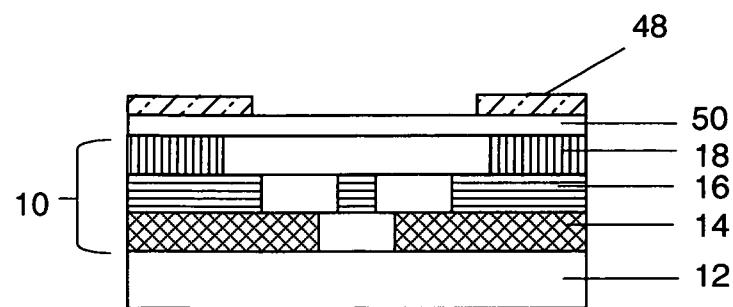
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**FIG. 7A****FIG. 7B****FIG. 7C****FIG. 7D**

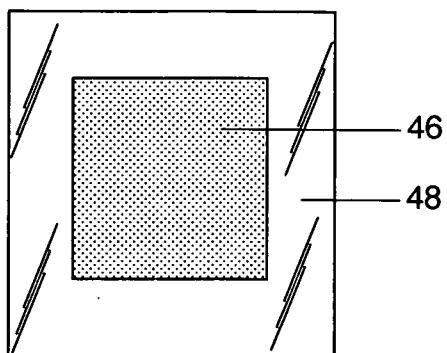
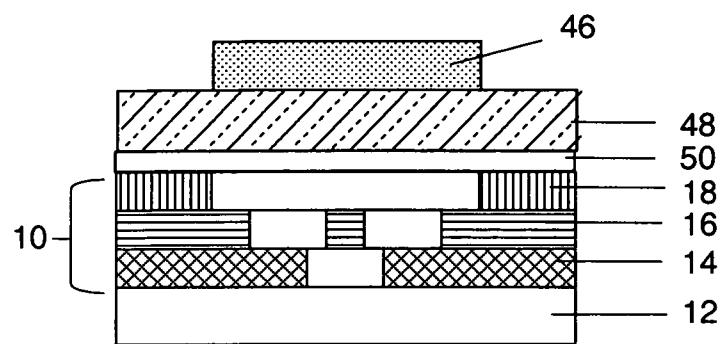
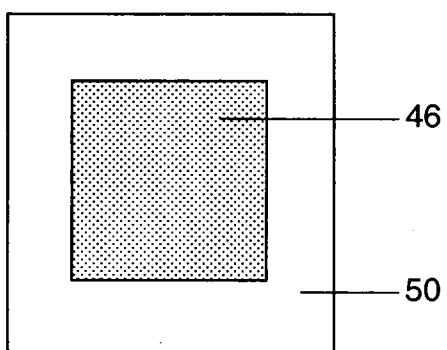
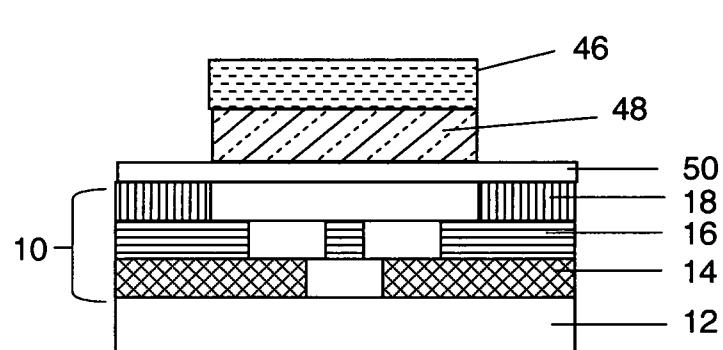
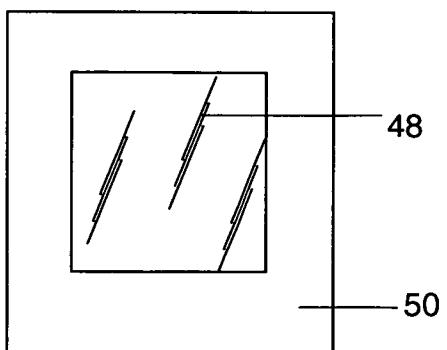
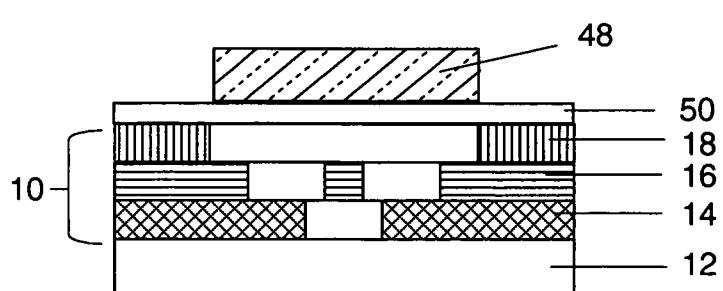
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**FIG. 8A****FIG. 8B****FIG. 8C****FIG. 8D****FIG. 8E****FIG. 8F****FIG. 8G****FIG. 8H**

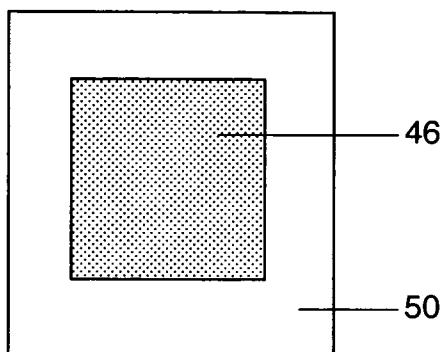
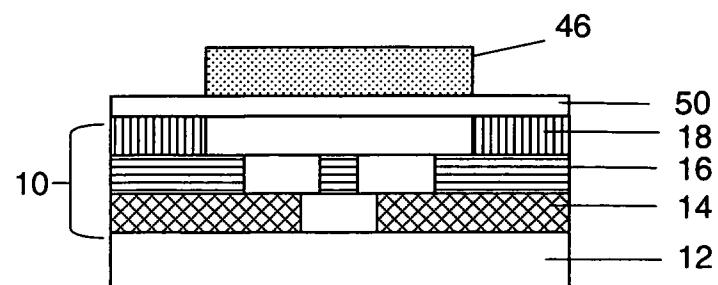
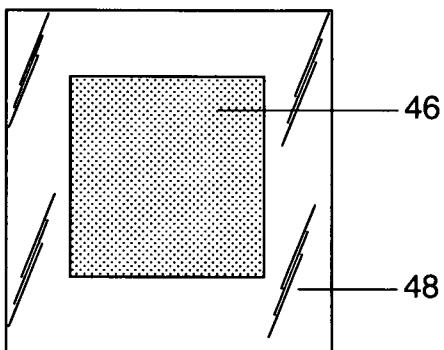
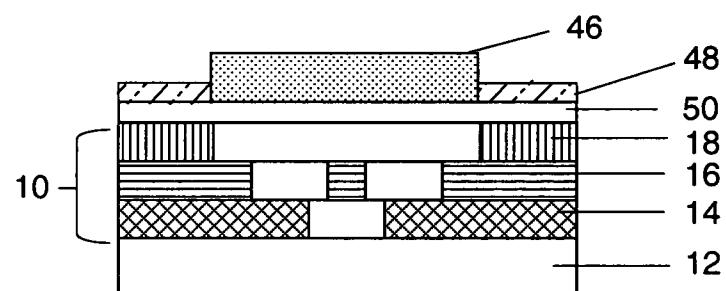
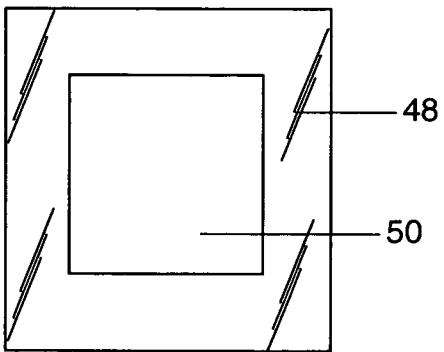
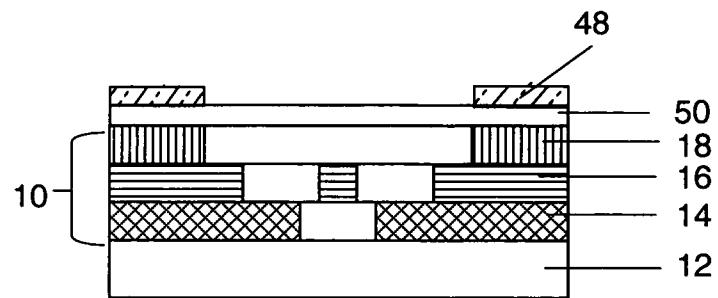
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**FIG. 9A****FIG. 9B****FIG. 9C****FIG. 9D****FIG. 9E****FIG. 9F**

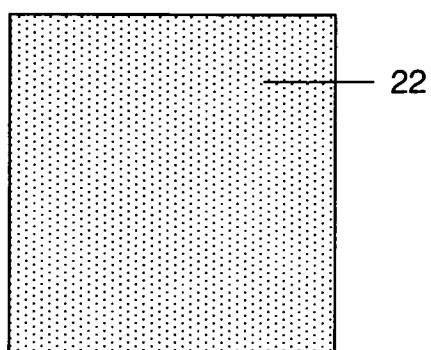
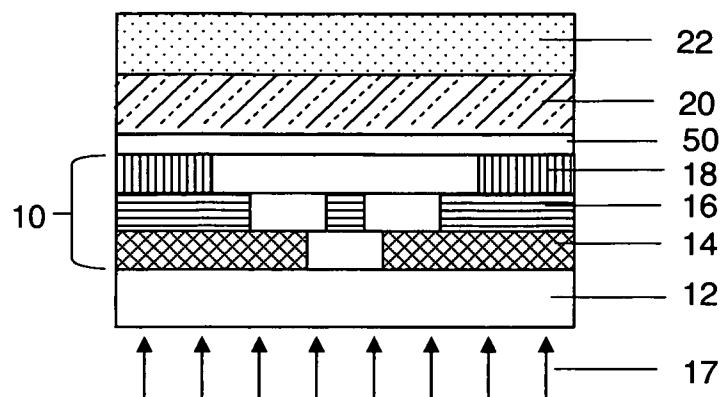
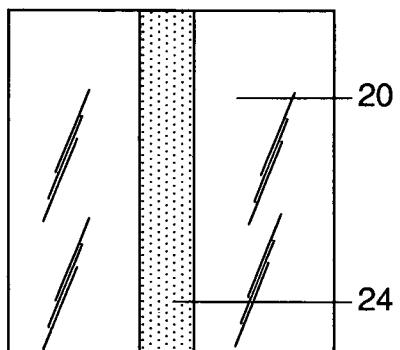
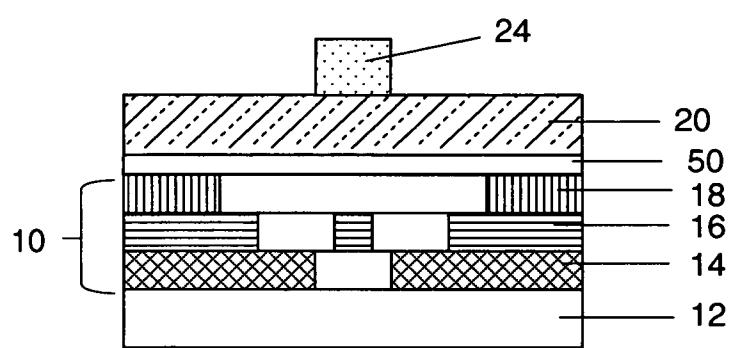
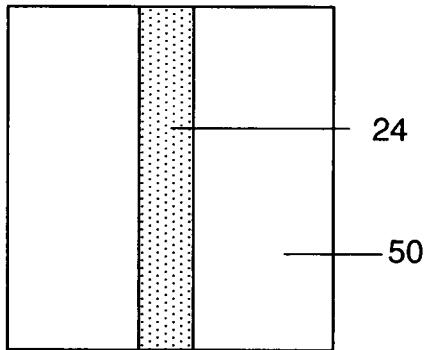
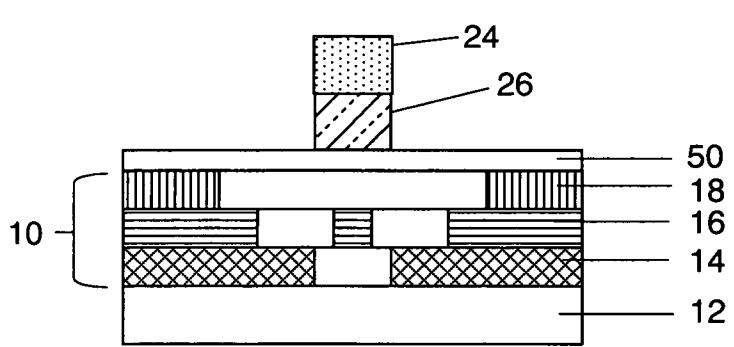
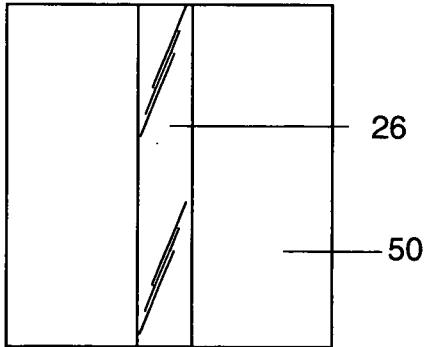
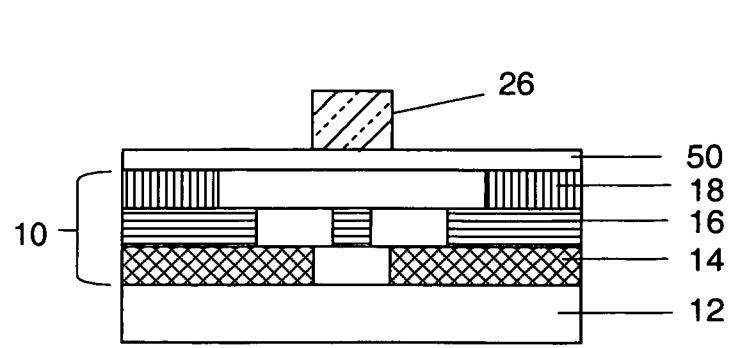
10/16

**FIG. 10A****FIG. 10B****FIG. 10C****FIG. 10D****FIG. 10E****FIG. 10F**

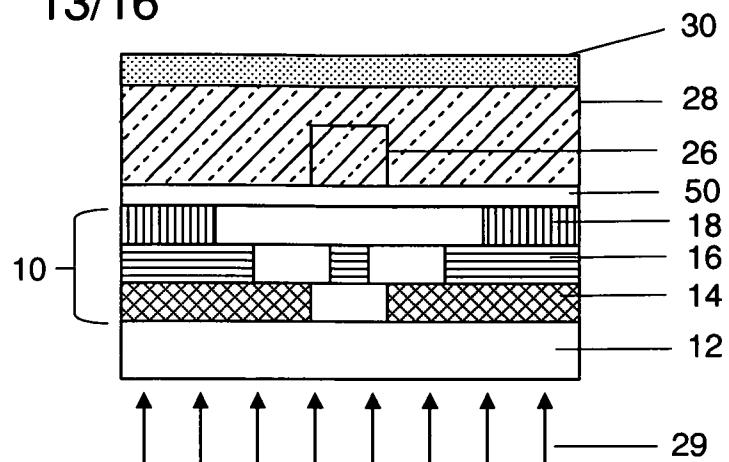
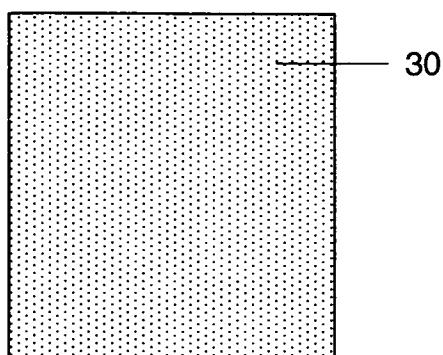
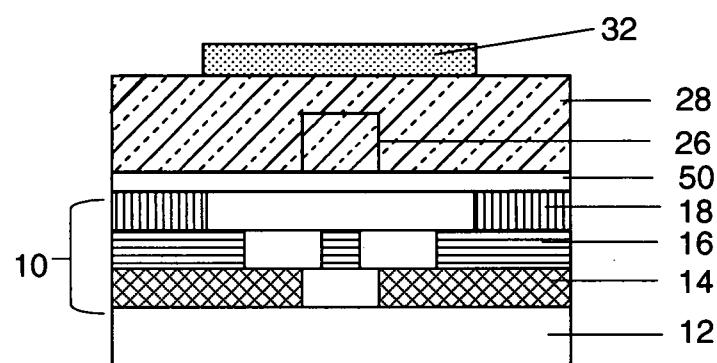
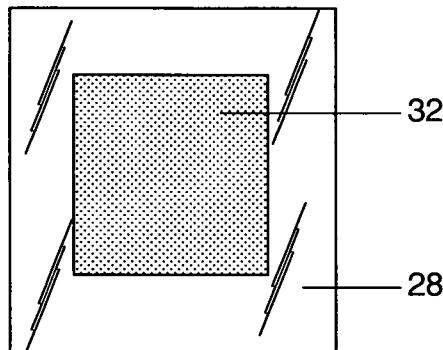
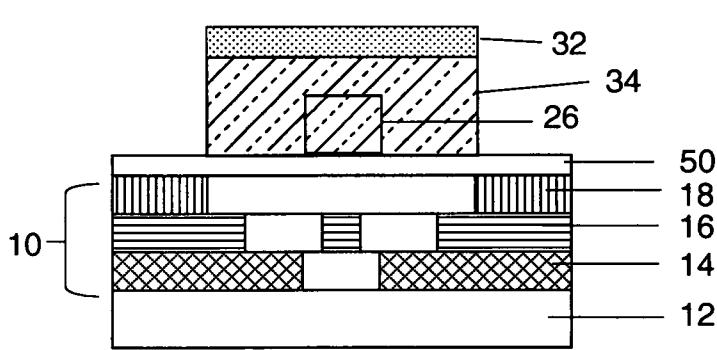
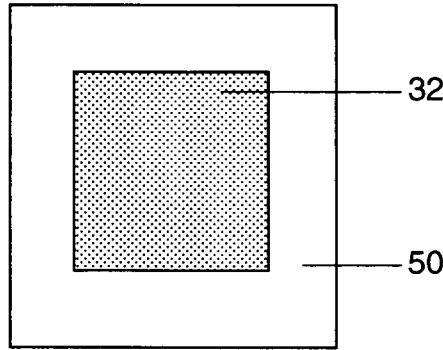
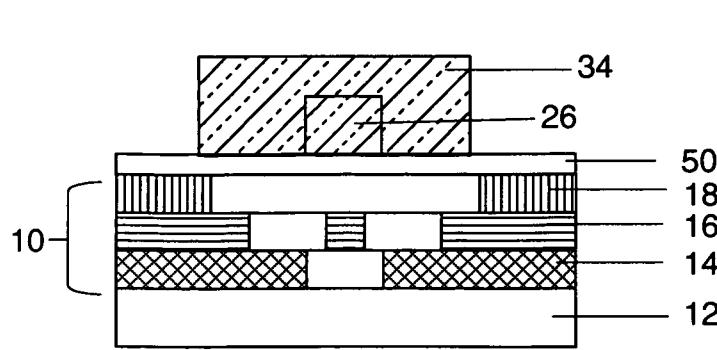
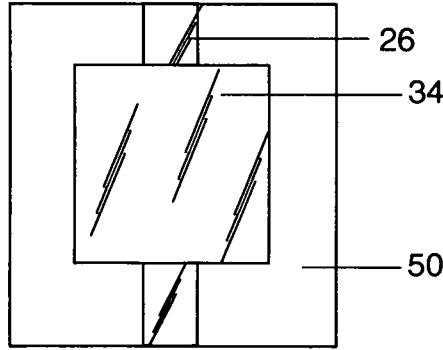
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**FIG. 11A****FIG. 11B****FIG. 11C****FIG. 11D****FIG. 11E****FIG. 11F**

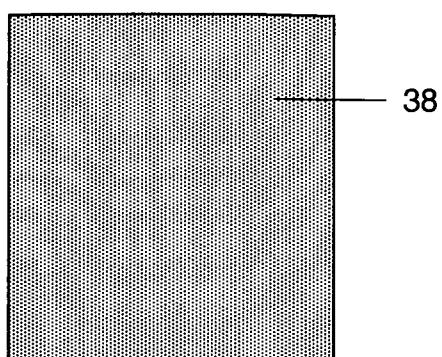
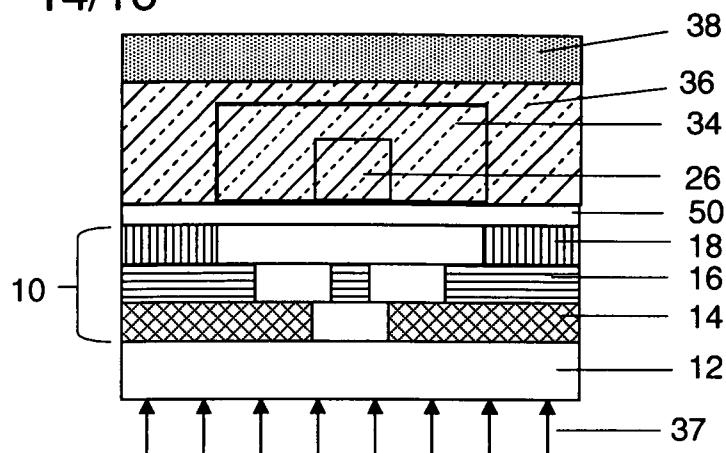
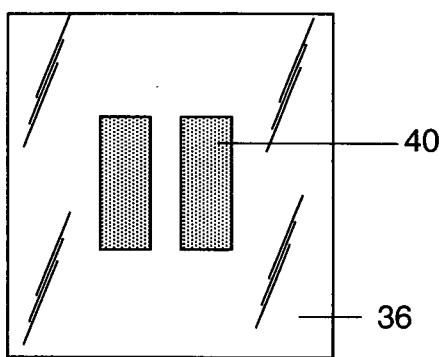
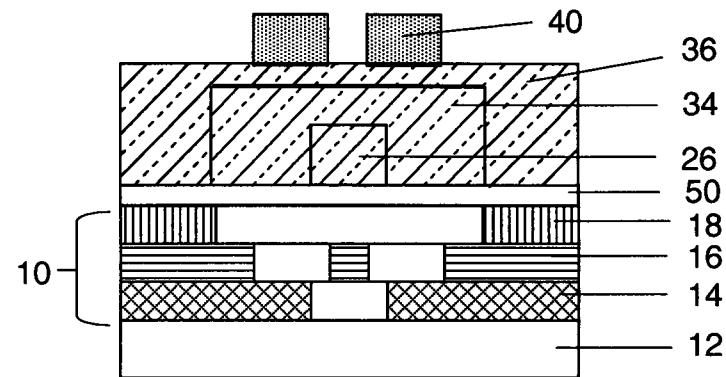
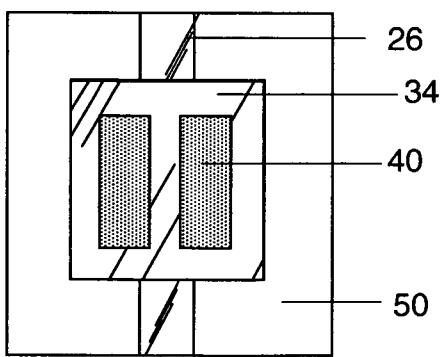
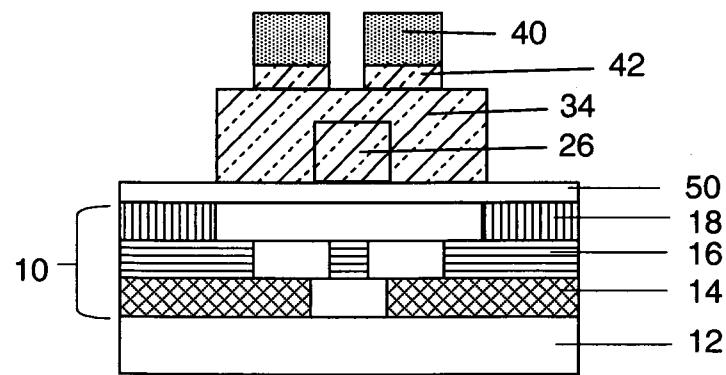
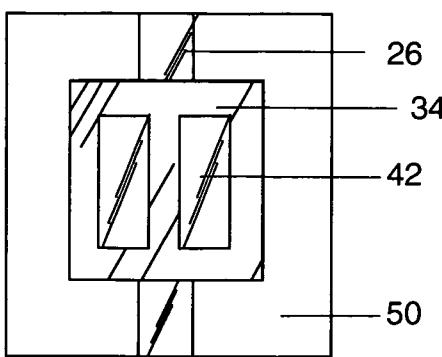
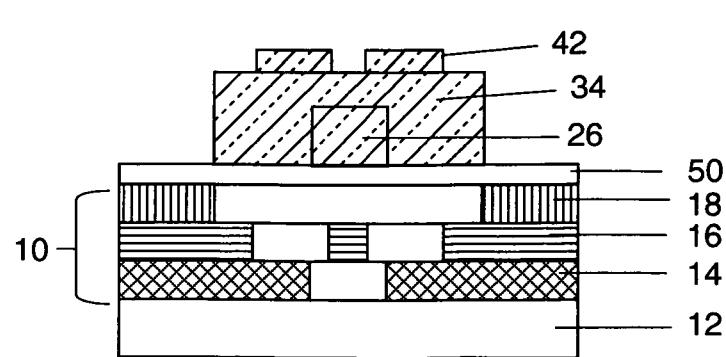
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**FIG. 12A****FIG. 12B****FIG. 12C****FIG. 12D****FIG. 12E****FIG. 12F****FIG. 12G****FIG. 12H**

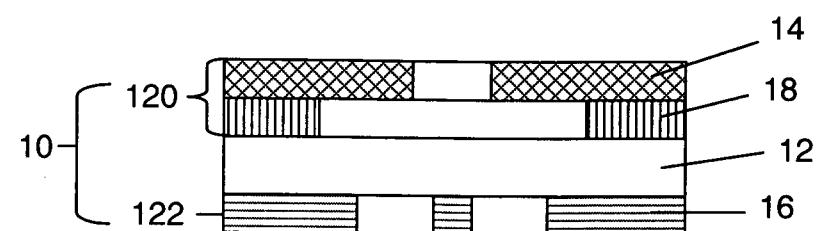
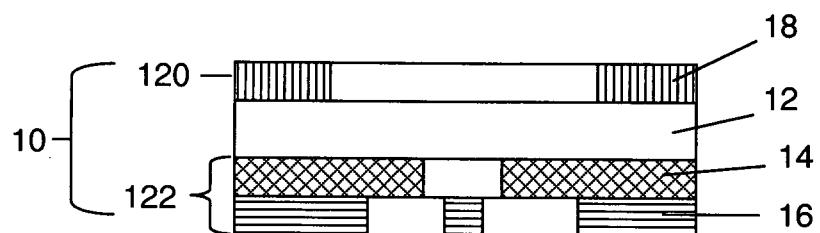
13/16

**FIG. 13A****FIG. 13B****FIG. 13C****FIG. 13D****FIG. 13E****FIG. 13F****FIG. 13G****FIG. 13H**

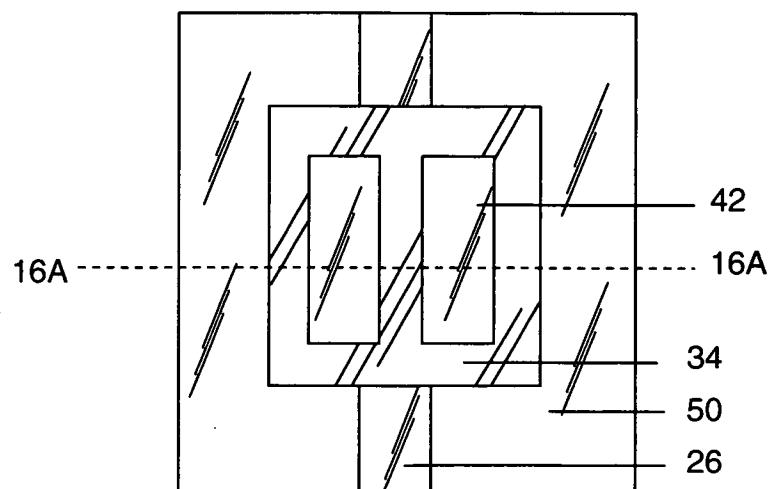
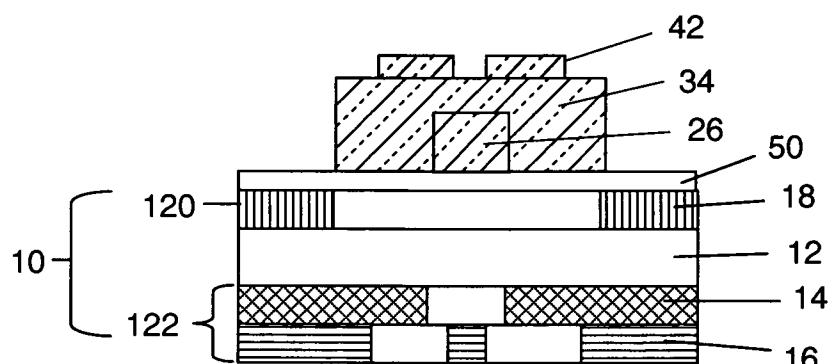
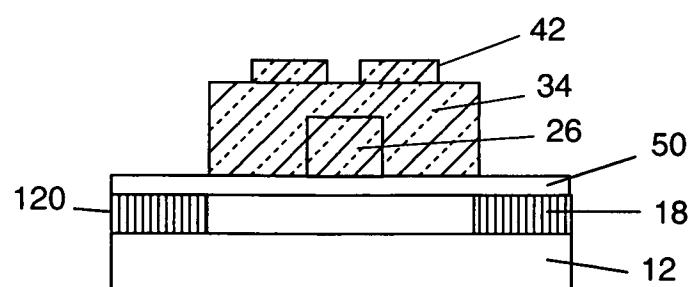
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**FIG. 14A****FIG. 14B****FIG. 14C****FIG. 14D****FIG. 14E****FIG. 14F****FIG. 14G****FIG. 14H**

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**FIG. 15A****FIG. 15B**

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**FIG. 16****FIG. 16A****FIG. 16B**

# INTERNATIONAL SEARCH REPORT

International application No  
PCT/US2008/012659

**A. CLASSIFICATION OF SUBJECT MATTER**  
INV. G03F7/00 G03F7/20 H01L21/77

According to International Patent Classification (IPC) or to both national classification and IPC

**B. FIELDS SEARCHED**

Minimum documentation searched (classification system followed by classification symbols)  
G03F H01L G02F

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EP0-Internal

**C. DOCUMENTS CONSIDERED TO BE RELEVANT**

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	US 2002/017645 A1 (YAMAZAKI SHUNPEI [JP] ET AL) 14 February 2002 (2002-02-14) paragraphs [0052] - [0058]; figure 4	17-23
P, X	US 2007/292998 A1 (YU WEI-SHENG [TW] ET AL) 20 December 2007 (2007-12-20) paragraph [0028]	1
A	EP 0 450 840 A (SEIKO EPSON CORP [JP]) 9 October 1991 (1991-10-09) column 5, lines 20-50, OKAY; figure 3	1
A	US 4 673 253 A (TANABE HIROSHI [JP] ET AL) 16 June 1987 (1987-06-16) the whole document	1
	-/-	

Further documents are listed in the continuation of Box C.

See patent family annex.

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- \*A\* document defining the general state of the art which is not considered to be of particular relevance
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\*X\* document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

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Date of the actual completion of the international search

Date of mailing of the international search report

18 February 2009

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